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TABLE OF CONTENTS

Effect of Er and Ni-CNTs on the Interfacial Reaction and Growth Behavior of Sn58Bi/Cu Intermetallic Compound Layers	1
<i>Qi Li, Haitao Gao, Xueying Zhang, FengMei Liu, Zhihong Cai, Jianglong Yi</i>	
A Critical Assessment of Graphene Based Heat Pipes for Electronics and Power Module Cooling Applications.....	8
<i>Zhiyang Shen, Hongfeng Zhang, Amos Nkansah, Jiajia Chen, Jin Chen, Johan Liu</i>	
Theoretical Studies and Root Cause Identification of the Pinhole Defects on Al Bondpads in Wafer Fabrication and Packaging Processes	13
<i>Yunan Hua, Lois Liao, Chao Zhu, Linhua Zhang, Xiaodan Luo, Xiaomin Li, Meihua Wu</i>	
Study on the Failure Mechanism and Characteristics of Electrochemical Migration of Electronic Package Structures in Humid Environment.....	17
<i>Yuchen Xi, Guoxu Zhang, Fei Jia</i>	
A Junction Temperature Prediction Model for 3D Stacked Packaging Chip Based on Thermal Resistance Matrix	22
<i>Jiahao Liu, Fangzhou Chen, Hao Zhao, Hui Xiao, He Diao, Xiangxiang Zhong, Fengyi Wang, Hao Liu, Xiaotong Guo</i>	
Design and Optimization of Cell and Multiple-Zone Gradient Modulation Field Limiting ring(MGM-FLR) Termination for 1700V/10A 4H-SiC Merged PiN/Schottky (MPS) Diodes	27
<i>Bofeng Zheng, Houcai Luo, Huan Wu, Jingping Zhang, Xianping Chen, Lei Lang</i>	
Copper Raw Material with Elongation Factor to Improve Delamination Performance	32
<i>Linda Li, Kim Ng, Tina Li</i>	
Evaluation of the Influence of the Reliability Application of a Thermal Insulation Adhesive on the Reliability of Solder Joints	35
<i>Sheng Zhang, Chenhui Zhang, Fei Zhang, Shuai Chen, Zhidan Liu, Xing Jin</i>	
Test and Evaluation of Process Adaptability and Environmental Adaptability for Reliability Application of a Thermal Insulation Adhesive	40
<i>Sheng Zhang, Chenhui Zhang, Zhidan Liu, Fei Zhang, Shuai Chen, Xing Jin</i>	
Analysis of 3D Stacking Technology and TSV Technology.....	46
<i>Hui Xuan, Guohua Gao, Xiaoyong Miao</i>	
Research for the Development of Advanced Packaging Material Testing Technology and Standardization.....	50
<i>Zhaoning Sun, Peijing Liu, Chengcheng Chen, Zhenbo Zhao, Meizhen Xiao, Hao Zhao</i>	
Characterization Tests of Electrodeless Discharge Lamps for Hyperspectral Sensors Spaceborne Calibration.....	55
<i>Ziliang Pang, Jinkun Zheng, YongLin Bai</i>	
Reflow Soldering Using Flux-Sprayed Solder Preforms.....	58
<i>Fred Fuliang Le, Zunyu Guan, Haibin Chen, Haima Santican, Vegneswary A-P Ramalingam</i>	
On-Die Power-Rails Isolation Using Package Loop Inductance	64
<i>Vinod Arjun Huddar, Shinyoung Park</i>	

Technology Development of Wafer-Level Ultra-high Density Fan-out (UHDFO) Package.....	67
<i>Dongzhi Fu, Shuying Ma, Yanjiao Zhao, Shiquan Yang, Jiulin Shen, Zhiyi Xiao</i>	
Achieving Non-Underfill SMT Process for Large Size Packages by Creative Package Pin Map and PCB Pad Designs.....	72
<i>Hingbin Shi, Chao Yang, Jianrui Zhang</i>	
Board Level Solder Joint Thermal Fatigue Reliability Improvement by Optimizing PCB Pad Size and Solder Paste Stencil Mask Designs.....	78
<i>Mengyuan Li, Hongbin Shi, Xiang Lv</i>	
Underfill Flow Numerical Simulation for Achieving Board Level Low Cost and High Reliability of Mobile Devices.....	83
<i>Yiming Jiang, Hongbin Shi, Xiang Lv</i>	
Studies of Atomic Force Microscopy and Application in Advanced Packaging, Materials Characterization and Failure Analysis.....	90
<i>Yunan Hua, Lois Liao, Lei Zhu, Linhua Zhang, Xiaodan Luo, Yanfei Zhao, Meihua Wu, Xiaomin Li</i>	
Improvement of the Solderability of Aluminum Alloy, Nickel, Stainless Steel and Copper by Metallization of Silver and Nickel for Power Semiconductors.....	94
<i>Jincheng Li, Jing Qian, Dongfang Dai, Xuan Yang, Lei Lang, Peixuan Jiang, Xianping Chen</i>	
A Thin Film Metallization Process Development for Silicon Nitride Ceramic Substrates in Power Electronics Packaging.....	100
<i>Xin Chen, Donglin Zhang, Jiaqi Song, Tao Xu, Xin Tian, Xiuchen Zhao, Yongjun Huo</i>	
Chemical Reduction Preparation of Multi-Morphology Micro-Nano Silver Powders and Their Performance in Solar Cell Conductive Silver Pastes.....	105
<i>Siwei Tang, Panzheng Li, Haonan Dong, Zhe Huang, Yunzhu Ma, Wensheng Liu</i>	
A High-Performance Visible Framing ICCD Camera Base on the Image Intensifier.....	110
<i>Jinkun Zheng, Zhen Chen, Wenqiang Qin, Junjun Qin, Yonglin Bai, Bo Wang</i>	
The Effect Mechanism of Electron Irradiation on MEMS Comb-Type Capacitive Accelerometer.....	115
<i>Xuwei Zhao, Nannan Li, Lijuan Wang, Jianmin Song, Zhenkai Wang, Chaoyang Xing</i>	
Experimental Study on the Growth Behavior of Ni ₃ Sn ₄ Intermetallic Compound Within Single-Layer SnAg Micro Solder Bumps Considering Ultra-Long Time.....	120
<i>Yuxing Wang, Xiangou Zhang, Linwei Cao, Xiangyu Sun, Shun Li, Zhifeng Yao</i>	
High-Performance Silver Nanowire Flexible Transparent Electrodes Under Current Stress and the Application for Long Lifetime OLEDs.....	123
<i>Yilong Huang, Dongsheng Yang</i>	
Rough Interface Effect on High-Temperature Reliability of TSV for Electronic Packaging.....	127
<i>Weishan Lv, Xin Lei, Jiabin Liu, Yun Mou, Fulong Zhu</i>	
Enabling Zero Delamination Between Lead Frame Surface and Epoxy Molding Compound at Zero-Hour and MSL1 in Leadless Package.....	131
<i>Wenhao Lan, Wa-San Leung, Zhigang Li, Shaoqing Luo</i>	
Modeling Methodology for Mechanical Shock Reliability Enhancement Designs of Ultra-Large BGA Packages.....	135
<i>Jianghai Gu</i>	

Study on the Application of Auger Electron Spectroscopy in RDL Failure Analysis.....	139
<i>Yanfei Zhao, Lei Zhu, Qingrui Jiao, Younan Hua, Xiaomin Li</i>	
Effect of X-Rays Irradiation on the Reliability of 850nm High-speed VCSEL	144
<i>Jide Zhang, Wenyuan Liao, Shaohua Yang, Guoguang Lu, Xiaohua Wang, Zhipeng Wei</i>	
Contribution of Sintering Process to the Reliability of X7R BME-MLCCs with High-voltage	150
<i>Gang Jian, Lei Zhang, Shuhui Yu, Rong Sun, Zhenxiao Fu, Xiuhua Cao</i>	
A High Density QFP with Hybrid Lead.....	155
<i>Milan Ma, X.S. Pang, J.Z. Yao, Denis Bai, Yongchao Luo</i>	
Deposition Efficiency Study on Wafer Level Gold Plating Based on Cyanide-Free Electrolyte	162
<i>Zhaowei Jia, Junwei Sheng, Sen Yang, Jian Wang, David Wang</i>	
A Fast and Simple Method to Place Sub-Die Under Chip-let Architecture Based on Thermal Simulation	165
<i>Jiangcheng Cao, Hongtao Man, Xiaohu Wu</i>	
Radiated Emissions Prediction of an Electronic Packaging Based on Near-Field Scanning.....	170
<i>Di Wang, Xing-Chang Wei</i>	
Research on the Welding Technology of T/R Components Assembled with SIP Moulds	176
<i>Zhidan Liu, Zhiping Zhao, Fei Zhang, Shuai Chen</i>	
Design of Optoelectronic Chip Packaging and Integration Method Based on SiP Technology	180
<i>Hui Xuan, Miao Xiaoyong, Gao Guohua</i>	
Lifetime Model of Copper Pillar Micro-Bump Interconnects Under Bi-directional Pulse Current Stress	190
<i>Zhiwei Fu, Tongsen Hao, Qingzhong Xiao, Jile Xu, Bingjie Zheng, Jia-Yue Yang</i>	
Location Identification Method for Soldering Devices of SMT Based on ConvRes-UNet.....	195
<i>Yiqing Yang, Qiang Zhang, Kailin Pan</i>	
An Investigation on the on Dielectric, Ferroelectric Properties and Failure Mechanism for the 0805X7R Multi-Layer Ceramic Capacitor	201
<i>Pengfei Wang, Lei Zhang, Shuhui Yu, Rong Sun, Zhenxiao Fu, Xiuhua Cao</i>	
In Situ Nondestructive Study Interface Aging Mechanism of Polymeric Materials/nanocomposites Based on Dual-Beam Raman Spectroscopy	207
<i>Yuan Liu, Xiaoliang Zeng, Rong Sun, Binbin Zhou</i>	
Design of a Miniature High-Gain Quasi-Resonant Flyback Converter.....	211
<i>Peixuan Jiang, Renbin Yang, Jialu Wang, Yuheng Gao, Bo Gao, Xianping Chen</i>	
Prediction of Electromagnetic Leakage from Circuits Inside Package.....	217
<i>Si-Yao Tang, Xing-Chang Wei</i>	
Three-Point Bending Test Method Experimental Study for Package Strength and Crack Prediction Through Finite Element Analysis	220
<i>Minyan Wu, Yunpeng Shang, Tingzuo Tan, Yonghua Zhou</i>	
Study on Mechanical Properties and Microstructure Reliability of Composite Solder Under Multiple Reflow and High-Temperature Storage	226
<i>Jiaxing Wang, Long Zhang, Quanbin Yao, Pengrong Lin, Yingzhuo Huang, Xiaochen Xie</i>	

Study on Failure Modes of High Speed Optical Communication PCB.....	232
<i>Bo Zhou, Dingfeng Luo, Meizhen Xiao, Minjie Ning, Xiao He</i>	
Optimized Stencil Opening to Increase Solder Flowing Area for Solder Void Performance Improvement	236
<i>Jingwen Gan, David Wong, Chaochao Xu</i>	
Ripple-Control Multi-port Step-down Power Converter Design in Outdoor Power Supply Application.....	239
<i>Yuheng Gao, Peixuan Jiang, Jialu Wang, Lijin Cheng, Xianping Chen, Bo Gao</i>	
Cascode GaN Device's Electrical Performance Failure Caused by Package Degradation Under Repetitive Power Cycling Stress	245
<i>Yijun Shi, Shan Wu, Zhiyuan He, Zongqi Cai, Liye Cheng, Yunliang Rao, Qingzhong Xiao, Yiqiang Chen, Guoguang Lu</i>	
The Influence of Welding Interfacial Voids on the Thermal Conductivity of Space-Borne High-power Electronics	250
<i>Le Zhang, Guisheng Zhong, Dongchao Diwu, Rui Wang, Zhengping Chen, Zhansi Jin</i>	
Mechanical Properties of IGBT Module Under Temperature Shock Test Considering Residual Stress	256
<i>Rui Wang, XuGuang Liu, JinLong Yang, Jian Luo, YuChao Shi, Jing Wu</i>	
Design and H3TRB Test on 650V SiC-JBS Diodes	260
<i>Lei Lang, Houcai Luo, Xianping Chen</i>	
Microstructural Evolution and Shear Properties Degradation of Tin-Lead/Copper Solder Joints at Cryogenic Temperatures.....	265
<i>Hao He, Yufeng Liu, Yao Chen, Lu Han, Liang He, Jiahao Liu, Xiaotong Guo, Chunxu Jiang</i>	
Stress-Strain Analysis and Optimization of Laminated Solder Joints Under Random Vibration Load Based on Taguchi and Grey Correlation Method	270
<i>Liye Wu, Chunyue Huang, Xiaobin Liu, Lilin Wang, Xianjia Liu, Huaiquan Zhang</i>	
Fan-Out Embedded Bridge Solution for Chiplet/HBM Integration.....	276
<i>Mark Liao, Vito Lin, Andrew Kang, Long-Yuan Wang, Teny Shih, Y.P Wang</i>	
Development of Thermal Resistant Temporary Bonding Material for Fan-Out Wafer Level Packaging: Dual-curing and Dual-debonding Strategies Are Available	280
<i>Kang Li, Yun Bai, Qiang Liu, Guoming Jiang, Yanting Liu, Yalin Zeng, Wenxue Dai, Xuefan Wang, Guoping Zhang</i>	
Performance Enhancement of GaN/AlGa _N Multi-Quantum-well Ultraviolet Light-emitting Diodes by a Novel P-type Electron Blocking Layer with Graded Inverted V-shaped Structure.....	284
<i>Taiping Han, Yan Wang, Liang Yang, Bin Wang, Junlin Xue, Sicheng Yi, An Xie, Chunyan Cao</i>	
Effect of Pre-Welding Pulse on Microstructure and Mechanical Properties for Parallel Gap Resistance Welding Joint of GaAs Solar Cell and Ag Foil.....	289
<i>Yuhan Ding, Zhichao Wang, Xiaoran Li, Yi Wei, Chen Shen, Xueming Hua, Min Wang, Lin Wang, Bin Qian</i>	
Thermal Fatigue Behavior of Cu/Co-P/Sn/Co-P/Cu Solder Joint Interface with Crystalline/amorphous Co-P Coating	295
<i>Shuang Liu, Limin Ma, Cheng Zhen, Fu Guo</i>	

Improving Moldability by Regulating Thixotropy of Epoxy Molding Compounds.....	299
<i>Xiang Liu, Roger Lu, Guangchao Xie, Haiyong Gu</i>	
Effect of Isopropyl Alcohol, Acetic Acid and Sodium Dodecyl Sulfate on the Etching Rate and Surface Roughness of Z-Cut Quartz Etched by BOE Solution	303
<i>Dou Guangbin, Zhou Yike, Dong Yide</i>	
The Effect of Pore Defects on the Interfacial Thermal Resistance of GaN-Diamond Heterostructure	307
<i>Chao Yang, Pengfei Zhao, Jian Wang, Dezhi Ma, Zhiyuan He, Zhiwei Fu, Jia-Yue Yang</i>	
Selective Laser-Induced Etching of Borosilicate Glass in Hydrofluoric Acid.....	312
<i>Yue Zhan, Kuibo Yin, Meng Nie, Guangbin Dou</i>	
Welding Process Expert System Based on Industrial Internet and Neural Network.....	318
<i>XiaoChuan Xie, ShengJie Sun, JunShuai Chen, JunCheng Liu, HaiPing Lan</i>	
Optimization and Research on Warpage of Ultra-Thin Substrate.....	323
<i>Qiang Wei, Huan Yang, XiaoJian Ma, Weidong Liu, JiaChen Wang, PengKai Wang</i>	
Effect of Young's Modulus on the Reliability of Sintered Silver Joints: Simulation and Experiment	327
<i>Kuifu Cheng, Cheng Zhong, Yuning Zhang, Liang Xu, Xianwen Liang, Zhiqiang Lai, Dan Liu, Tao Zhao, Rong Sun</i>	
Study of the Shear Strength Behavior in Flip Chip Under Thermo-Mechano-electrical Coupling and Different Solder Height	332
<i>Bin Zhou, Jianxin Qiao, Yunkang Su, Dapeng Liu, Wentao Huang, Longqiu Li</i>	
Thermal Stress Analysis and Optimization of BGA Stacked Solder Joints Under Power Cyclic Loading.....	337
<i>Xianjia Liu, Chunyue Huang, Lilin Wang, Liye Wu, Xiaobin Liu, Huaquan Zhang</i>	
Research on Intelligent Detection Method for IC Surface Defects Based on Convolutional Neural Network.....	342
<i>Yue Zhao, Hongfeng Lv, Zhizhe Wang, Jun Luo</i>	
Thermal Cycle Reliability of Microwave Components in CBGA Package with Different Dispensing Methods for Spaceborne Radar	345
<i>Li Miao, Sun Xiaowei, Sun Yanlong, Zou Jiajia, Chen Gaiqing, Song Huidong, Fu Ren</i>	
Directly Electroplated Metallization on Through Glass Via (TGV) Using Silver Nanowires Conductive Composite as Seed Layer	350
<i>Zhiqiang Lai, Dan Liu, Tao Zhao, Yongjiang Zhang, Xianwen Liang, Rong Sun</i>	
High Energy Dissipation Composite Elastomer for Application as a Thermal Interface Material Through Solvent-Induced Dis-entanglement.....	356
<i>Weijian Wu, Hangqian Wang, Xiangliang Zeng, Zhifeng Hao, Jianfeng Fan, Linlin Ren</i>	
Study on the Curing Kinetics and Curing Behavior of Epoxy Conductive Adhesive Materials for Electronic Packaging and Their Impact on Conductivity	362
<i>Jiajia Zou, Mengqiu Huang, Dan Zhao, Fang Chen, Daochang Wang</i>	
Dielectric Properties and Reliability of Calcium-Doped BaTiO ₃ -based MLCCs with High Capacitance	367
<i>Yetong Lv, Lei Zhang, Pengfei Wang, Rong Sun, Shuhui Yu, Zhenxiao Fu, Xiuhua Cao</i>	

Low Modulus Polyimide Coating on Wedge Bond to Improve Wire Bond Robustness in Thermal Cycling	372
<i>Ou Dong, Zhiwen Li, Hans-Juergen Funke, Haibo Fan</i>	
Enhanced Reliability of Ultra-Thin BME-MLCCs Based on Low Oxygen Vacancy by Re-oxidation Process.....	376
<i>Xiong Huang, Lei Zhang, Shuhui Yu, Rong Sun, Zhenxiao Fu, Xiuhua Cao</i>	
Enabling Low-K Liner in Ultra-high Aspect Ratio TSVs by the Timing of Vacuum Treatment in the Vacuum-assisted Spin-coating Technique	380
<i>Ziyue Zhang, Zhiming Chen, Baoyan Yang, Yigang Hao, Yuwen Su, Yingtao Ding</i>	
Power Supply Design and Application Based on Piezoelectric Effect	384
<i>Xinxin Ma, Lijiao Gong, Wangwang Guo, Tong Yang</i>	
Structure Optimization Design of Interfacial Failure Resistance for Composite Film in Flexible Electronics.....	390
<i>Hongshi Ruan, Yangjian Xu, Xiaozhe Ju, Xing Chen, LiHua Liang</i>	
Effect of Zr ⁴⁺ Doping on Electrical Property of BaTiO ₃ -Based MLCC with High-voltage	396
<i>Chun Wang, Xiong Huang, Lei Zhang, Rong Sun, Shuhui Yu, Zhenxiao Fu, Xiuhua Cao</i>	
Strain Threshold Test and Case Analysis of THT Component	402
<i>Wanchun Tian, Shiyu Wang, Peijiang Liu, Jiahao Liu, Jingxi Wu, Hao Zhao</i>	
Electrical Performance Enhancement Solution with FO-EB in HPC Application	406
<i>Po Yuan James Su, David Ho, Yu Po Wang, Jacy Pu, Teny Shih, Sam Lin</i>	
Fabrication of 45-Degree Integrated Mirrors for Three-Dimensional Board-Level Optical Interconnects Realizing Efficient Light Coupling	411
<i>Xiaofeng Liu, Hua Miao, Guodong Wang, Tengfei Yao, Jianhui Liu, Rong Sun</i>	
Effect of Filler Particle Size and Surface Functionalization on the Properties of Thermal Grease	416
<i>Xiangliang Zeng, Jianfeng Fan, Shipeng Rao, Linlin Ren, Xiaoliang Zeng, Rong Sun</i>	
Effects of Silver Paste Glass Additive Composition on Co-Firing Behavior of Silver Conductor LTCC Package.....	419
<i>Zhuofeng Liu, Wenxue Liang, Wei Li, Yan Xun, Fenglin Wang, Weijun Zhang</i>	
Research on Modeling and IP Technology for High-Speed Optical Interconnection Interfaces in Optoelectronic Microsystems.....	423
<i>Haoyan Wang, Yunong Ye, Wei Li, Zhiqiang Wang, Jie Liu</i>	
High Speed SerDes Design on Flip Chip Package Substrate	429
<i>Ming-Han Zhuang, Chia-Chu Lai, Ho-Chuan Lin, Chih Yuan Shih, Andrew Kang, Yu-Po Wang</i>	
Verification of a Chinese Copper-System LTCC.....	435
<i>Shicheng Yang, Peng Sun, Zepeng Xu, Jin Biao Pang, Meijuan Xu, Zhuo Lin</i>	
Conjugated Small Molecule Crystals as a Coupling Layer Between Carbon-Based Thermal Interface Materials and Heat Sink	439
<i>Daoqing Liu, Jingjing Zhang, Jianhui Zeng, Rong Sun, Jian-Bin Xu, Yimin Yao, Xiaoliang Zeng</i>	

Experimental Validation of a Simple Fractional Model for Viscoelastic Behavior of High Filled Polymer-Based Composites.....	444
<i>Jianfeng Fan, Weijian Wu, Xiangliang Zeng, Yunsong Pang, Yu Zhou, Rong Sun, Xiaoliang Zeng, Linlin Ren</i>	
Injection Molding Process Optimization of Plastic Packaging Device Based on GA and BP Neural Network.....	450
<i>Fu Ruyi, Huang Wei, Zhang Jian, Pan Kailin, Gong Yubing</i>	
In-Plane Heat Transfer Enhancement of Phosphor Layer in Transmissive Laser-excited White Lighting	456
<i>Weixian Zhao, Bin Xie, Run Hu, Xiaobing Luo</i>	
Simulation Application of Interconnected Structure of Microsystems Based on Artificial Neural Network Technology	461
<i>Yunong Ye, Jie Liu, Haoyan Wang, Miao Li, Zhiqiang Wang, Wei Li</i>	
Influence of Cu Heat Sink on Heat Dissipation of QFN Package	467
<i>Haoqin Ma, Ziyi Yuan, Dongyan Ding, Cheekiang Yew</i>	
Study of Waveguide Sizes for Silicon Based Micro-Ring Filters.....	472
<i>Zhan Li, Yiqing Yang, Kailin Pan</i>	
Effect of Thermal Interface Materials on Thermal Performance and Reliability of Large Size Flip Chips.....	478
<i>Jinyang Su, Siyuan Lu, Canwen Wang, Wenhui Zhu, Liancheng Wang</i>	
Case Analysis and Improvement of Silver Migration in Resistors	484
<i>Chaohui Hu, Xiaoxiao Guan</i>	
High-Performance Thermal Interface Material with a Radial Filler Skeleton.....	489
<i>Jingjing Zhang, Daoqing Liu, Jianhui Zeng, Xiaoliang Zeng, Jian-Bin Xu, Yimin Yao, Rong Sun</i>	
Ablation Behaviour of Photosensitive Materials in Laser Debonding Processes for Advanced Packaging	494
<i>Fangcheng Wang, Qiang Liu, Xuefan Wang, Wenxue Dai, Guoping Zhang, Rong Sun</i>	
A Crosstalk Mitigation Method of DDR5 in Large Size LGA Package	499
<i>Keqing Ouyang, Shineng Ma, Feng Wu, Chao Lei, Jiangtao Zhang, Jian Pang</i>	
Effect of Insulating Material and Structure on the Reliability of Silicon Through Hole Under Thermal Stress.....	503
<i>Zongyang Li, Quanbin Yao, Pengrong Lin, Yingzhuo Huang, Xiaochen Xie, Zhibo Qu, Shuang Xie, Jinxiao Meng</i>	
Design Optimization for Dual Clip Flat Lead Package Assembly by Simulation	508
<i>Hing Suan Cheam, Haibo Fan</i>	
Phosphor-In-glass Film on AlN Substrate for High-luminance White Laser Lighting.....	512
<i>Zikang Yu, Yang Peng, Mingxiang Chen</i>	
Chlorine and Sulfur Effects on Silver Bonding Wire Reliability.....	516
<i>Jinzhi Loia Liao, Bisheng Wang, Xi Zhang, Younan Hua, Xiaomin Li</i>	
Power Noise Coupling Simulation of DDR4 for FCBGA Packaging	520
<i>Jianguo Zhang, Xie Meng, Qiang Chen, Jian Pang</i>	

Temperature Dependence of Thermal Conductivity for Low-K Dielectric Materials	524
<i>Chaoyue Ji, Shizhao Wang, Xintian Cai, Zhen Wan, Sheng Liu</i>	
High Temperature Storage Simulation and Strain Analysis of Solder Ball in Fan-Out Wafer Level Package (FOWLP)	529
<i>Peng Su, Cheng Xu, Meiyang Su, Fengwei Dai, Peng Sun, Liqiang Cao</i>	
4x4 Millimeter-Wave Patch Antenna Array for 5G Communication.....	533
<i>Ningning Yin, Tianfang Chen, Cheng Xu, Hongwei Zhang, Fengwei Dai, Peng Sun</i>	
Sidewall Chipping Investigation & Challenges on 100um Thin Low-K Wafer with DAF	537
<i>Hongbin Xia, Yongbing Wu, Linna Yuan</i>	
Study of TSV Interconnection Structure Based on Coupled High Temperature and Random Vibration Loading Conditions	541
<i>Bin Wang, Chunyue Huang, Chao Gao, Liye Wu, Xiaobin Liu, Xianjia Liu</i>	
Temperature Prediction Model of Sheep Barn in Winter Based on Neural Network	546
<i>Honglei Cen, Jingbin Li, Zichen Liu, Jing Nie, Qiang Cai</i>	
TGV Filling Process Based on Low Temperature Conductive Silver Paste	551
<i>Chen Yu, Wei Li, Tingting Yang, Heng Wu, Daquan Yu</i>	
Research on Quality Control of Thermal Ultrasonic Wire Bonding Based on PFMEA and SPC	555
<i>Xiaoran Cheng, Zhimin Ding, Chao Duan, Zhaoxi Wu, Yaning Wu, Meng Meng</i>	
Package Warpage and Low-K Stress Investigation Under Thermo-Compression Bonding with Non-Conductive Paste Process	561
<i>Siyuan Lu, Canwen Wang, Jinyang Su, Huapeng Chen, Wenhui Zhu, Liancheng Wang</i>	
Study on Picosecond Pulsed Laser Grooving Technology for Low-K Silicon Wafer.....	566
<i>Canwen Wang, Jinyang Su, Siyuan Lu, Wenhui Zhu, Liancheng Wang</i>	
Design and Research of Oval Flip Chip Solder Bump	571
<i>Guoshuai Li, Linghui Zheng, Lina Wang</i>	
Direct Soldering of 5A06 Al Alloy Using a Ti Alloy Mesh Reinforced SAC305 Composite Solder	574
<i>Xing Xu, Bangfu Xi, Gaiqing Chen, Yong Xiao</i>	
A Novel Circular Position Sensitive Detector for Continuously High-Precision Angle Measurement	578
<i>Xiangxu Meng, Siwei Sun, Xuetao Yan, Peng Yang, Fengman Liu, Liqiang Cao</i>	
An Ultra-Thin Vapor Chamber with Oriented Spiral Woven Wick for Microelectronic Heat Dissipation.....	582
<i>Caiman Yan, Haoyi Huang, Hang Liu, Hongjian Leng, Xuepeng Yuan, Yong Tang, Yifu Liang</i>	
Research on Simulation of Cu/SiO ₂ Hybrid Bonding Process and Interface Failure Mechanism by Finite Element Analysis.....	587
<i>Haozhong Wang, Hongtao Chen, Junshan Xiang, Xiaofeng Yang</i>	
Reliability Study of Through Glass Vias Under High Current Density	594
<i>Junshan Xiang, Hongtao Chen, Haozhong Wang, Xiaofeng Yang</i>	
A Novel Ultra-Thin Vapor Chamber Based on Graphite Copper-clad Film for Thermal Management in Electronic Devices.....	599
<i>Yifu Liang, Jingjing Bai, Xiaolong Liu, Shengrong Xiao, Xuepeng Yuan, Yong Tang, Caiman Yan</i>	

Quantitative Analysis of the Interface Strength of Ultra-Thin Dielectric Films Based on Fan-out Packaging	604
<i>Zhanxing Sun, Fei Ding, Rui Ma, Qidong Wang, Xiangmeng Jing, Meiyong Su, Liqiang Cao</i>	
Research on the Electromigration Failure of W Interconnects Under High-Temperature Environment	610
<i>Wang Yong, Jiantao Zeng, Xiaoyang Liu, Yike Fang, Lihua Liang, Yuanxiang Zhang</i>	
A Low-Cost Spin-on-glass (SOG) Liner Deposited by Vacuum-assisted Spin Coating Technique for Via-last Ultra-high Aspect Ratio Through-silicon Vias	616
<i>Xuyan Chen, Yingtao Ding, Ziyue Zhang, Lei Xiao, Han Wang, Zhiming Chen</i>	
Selective Wet Etching Technology in 3D NAND Flash Manufacturing.....	620
<i>Zihan Zhou, Silin Han, Yunwen Wu, Tao Hang, Huiqin Ling, Jie Guo, Su Wang, Ming Li</i>	
Anti-Oxidation Property of Nanotwinned Copper Micro-cone Array for Low-temperature Bonding	625
<i>Peixin Chen, Hongqi Sun, Mengya Dong, Tao Hang, Yunwen Wu, Ming Li</i>	
Effect of Microstructure on Sensitivity of Flexible Capacitive Pressure Sensor	629
<i>Jiantao Zeng, Yong Wang, Xiaoyang Liu, Yike Fang, Lihua Liang, Yuanxiang Zhang</i>	
Interconnection Performance of Copper Core Solder Joints in Ball-Grid-Array Package	635
<i>Qifan Wu, Chunyan Yin, Xuefei Ming, Zheng Ke, Jiachang Zhu, Guangbin Dou</i>	
Time-Of-Flight Mass Spectroscopic Studies of Non-Stick on Pad Issues in Wire Bonding	641
<i>Lei Zhu, Ling Ling Teo, Eric Lau, Yanfei Zhao, Younan Hua, Xiaomin Li</i>	
A Subpixel Edge Detection Algorithm to Test the Accuracy of Semiconductor Packaging Equipment	645
<i>Shikang Jin, Wei Zhou</i>	
Thermo-Mechanical Fatigue Failure Simulation and Life Prediction of Solder Joints Using the Maximum Entropy Fracture Model.....	651
<i>Xing Chen, Guixiang Xu, Hongshi Ruan, Chengkai Shen, Xiaozhe Ju, Yangjian Xu</i>	
Numerical Simulation of Solder Ball and RDL on Fan-Out Wafer Level Package Under Random Vibration.....	657
<i>Shuai Yang, Cheng Xu, Meiyong Su, Fengwei Dai, Peng Sun, Liqiang Cao</i>	
Effects of Porosity on Thermal Resistance Aging at Submicron Silver Interfaces.....	661
<i>Jian Wang, Mowen Zhang, Chao Yang, Zhiyuan He, Zhiwei Fu, Jia-Yue Yang</i>	
Study on Low-Temperature Bonding and Reliability of Nano-Twin Copper Micro-Cone Array.....	666
<i>Chongyang Li, Anmin Hu, Tao Hang, Yunwen Wu, Ming Li</i>	
Theoretical Analysis and Prediction for Thermal Stress of Sintered Silver Interconnection Structure Based on Modified Suhir's Solution	670
<i>Jiahui Wei, Yanwei Dai, Fei Qin</i>	
Research on the Electrical Performance of Flexible Metal Arrays.....	675
<i>Chengqi Ge, Caiping Huang, ZhaoLing Huang, Guolin Zhao, Houlin Long, Qi Zeng</i>	
Toward Next Generation Interconnection Technology: Ag/Cu Sinter Joining and Their Innovative Application	681
<i>Yue Gao, Jianbo Xin, Yiting He, Jing Zhang, Yang Liu</i>	

Carbazole-Grafted Polyimide with Enhanced Adhesion to Smooth Copper	685
<i>Zimeng He, Xialei Lv, Ao Zhong, Jinhui Li, Guoping Zhang, Rong Sun</i>	
Research on Genetic Algorithm for Feedforward Parameter Tuning in XY Motion Platform	689
<i>Wei Zhou, Huan Liu, HaiYuan He</i>	
Studies and Application of a Novel Failure Localization Method for 3D Stacked IC Chips.....	695
<i>Linhua Zhang, Younan Hua, Xiaomin Li</i>	
Non-Wet Simulation and Risk Prediction of 2.5D Package	698
<i>Qianjin Huang, Cheng Xu, Meiyang Su, Fengwei Dai, Peng Sun, Liqiang Cao</i>	
Thermal Performance Optimization Analysis of Double-Sided Heat Dissipation SiC Power Module for Vehicle	701
<i>Shuaiyang Chen, Dongjing Liu, Hao Li, Fu Zhou, Hong Chen, Daoguo Yang</i>	
FOStrip Technique for Low-Cost Fan-Out Package.....	705
<i>I-Hung Lin, Yu-Tai Chen, Ji-Ting Huang, Hsiang-Hua Lu, Ying-Chieh Pan, Chien-Hui Wang, Tom Ni</i>	
The Thermal Transient Measurement for the Carbon Fiber-Based Thermal Interface Materials in Electronic Packaging Structures	709
<i>Yunsong Pang, Rong Sun, Xiaoliang Zeng, Shangqiang Yang, Aixiang Sun, Yong Cao</i>	
Research on Sliding Mode Control Algorithm of Permanent Magnet Synchronous Linear Motor Based on Fuzzy Switching Gain Adjustment	713
<i>Huan Liu, Shikang Jin</i>	
Mode I Fracture of Graphene Reinforced Sn-Ag-Cu Solder Joints.....	718
<i>Jianfeng Wang, Yanwei Dai, Fei Qin, Kui Li</i>	
Thickness Effect on Shear Fracture Toughness of Sintered Silver Joints.....	723
<i>Rong Kang, Yanwei Dai, Fei Qin, Yanning Li</i>	
Optimizing Heat Source Arrangement for 3D ICs with Irregular Structures Using Machine Learning Methods.....	728
<i>Xixin Rao, Huizhong Liu, Jianhao Song, Cheng Jin, Chengdi Xiao</i>	
A Failure Analysis of Solder Flow in DC-DC Power Module.....	734
<i>Jiao Shaoling, Liu Wei, Wen Tao, Zhu Jia</i>	
An Isogeometric Boundary Element Scheme for Transient Heat Transfer Problems in Electronic Packaging	738
<i>Hao Xu, Yanpeng Gong, Yuguo Kou, Fei Qin</i>	
Fine Pitch Wafer-To-Wafer Hybrid Bonding for Three-Dimensional Integration	743
<i>Xiaofan Jiang, Zeming Tao, Tian Yu, Binbin Jiang, Yi Zhong, Daquan Yu</i>	
Stress Analysis and Geometrical Parameter Optimization of LGA Solder Joint Under Thermal Cycle Condition.....	747
<i>Jingyi Lan, Chunyue Huang, Shupeiyin, Shuyi Li, Xianjia Liu</i>	
Reliability Modeling of High Power DUV LED Chips Based on New Thin Film Packaging Technology	752
<i>Shuaiyi Pan, Huimin Xu, Xin Tan, Haoran Ma, Xiaochuan Xia, Hongwei Liang</i>	

Preparation and Sintering Performance of Micro-Nano Hybrid Copper Particles for Third-generation Semiconductor Package Interconnects	756
<i>Kai Yang, Yu Zhang, Zhongwei Huang, Linfeng Peng, Guanghan Huang, Chengqiang Cui, Guannan Yang</i>	
Epoxy Adhesive of High T_g for Electronic Packaging with Stress Relaxation and Self-Healing.....	762
<i>Hui Xu, Yanzhe Luo, Zhibo Sun, Zhu Mao, Jifeng Chen, Bo Tian, Pengli Zhu, Rong Sun</i>	
Improving the Interface Bonding Strength of Epoxy Adhesives for Electronic Packaging.....	768
<i>Yanzhe Luo, Hui Xu, Zhu Mao, Kaixuan Nie, Yi Ning, Zhongyu Li, Pengli Zhu, Rong Sun</i>	
Nonvolatile Memory Devices Based on Two-Dimensional WSe_2/MoS_2 Van Der Waals Heterostructure	773
<i>Sixian He, Pu Feng, Jicun Lu, Aidang Shan, Liancheng Zhao, Ming Li, Liming Gao</i>	
Copper Submicron Particle Pastes with Organic Compounds as Anti-Oxidative Additive for Cu-Cu Bonding in Air.....	777
<i>Xiaocun Wang, Fei Xiao</i>	
Optimal Scheduling of Microgrids Based on the Trading Mechanism of the Reputation Point System Method.....	782
<i>Dongmei Yan, Hongkun Wang, Hong Zhang, Yujie Gao, Mi Zhao, Zhenhua Lei</i>	
Study on the Control Method of Moisture Content in Microwave Modules	788
<i>Chuanwei Wang, Zhixian Min, Jiafu Jin, Chenyu Li</i>	
Etching Scallop-Less nano-TSV with F/O Coupling Plasma	791
<i>Yang Wang, Ziyu Liu, Jinzhu Li, Qingqing Sun, Lin Chen, David Wei Zhang</i>	
A Combined Experimental and Analytical Study of Residual Strains Developed in Encapsulated Structures.....	795
<i>Xiang Li, Hua Zhong, Xianhang Zhao, Xin Liu, Yuefang Li</i>	
Suppression of Kirkendall Voids at the Interface of Sn/nc-Cu Solder Joint	798
<i>Xinwei Tian, Shi Chen, Yuanyuan Qiao, Longjiang Zou, Ning Zhao</i>	
Research on Heat Dissipation Performance of Double-Sided Cooling IGBT Module.....	801
<i>Zuoyi Huang, Tong An, Fei Qin, Yanpeng Gong, Yanwei Dai, Zhen Wang</i>	
Microstructure and Properties of Sn3.0Ag0.5Cu Micro-Bumps with Nickel-coated Graphite and Nickel-coated Carbon Fibers Additions.....	805
<i>Yihui Du, Xiaoliang Ji, Yishu Wang, Fu Guo</i>	
Numerical Simulation of Bonding Wire Lift-Off of IGBT Under Power Cycling	810
<i>Shengjun Zhao, Tong An, Fei Qin, Zhen Wang</i>	
A Comprehensive Study of Interface Damage at Cu/Polyimide Interface in Redistribution Layers of Fan-Out Wafer Level Packaging.....	814
<i>Shilu Zhou, Cheng Zhong, Liang Shan, Guoping Zhang, Jibao Lu, Rong Sun</i>	
Strain Engineering for Modulating Electronic and Optoelectronic Properties of Monolayer InSe	819
<i>Siyuan Xu, Tuobei Sun, Junfeng Li, Tao Lin, Huiru Yang, Huaiyu Ye</i>	
Study on the Correlation Between the Ball Collapse Height and the Coplanarity Control Requirements for PBGA Reflow Soldering.....	824
<i>Guanghui He, Hui Xu, Hongqin Wang, Zengxiang Zheng, Qiaomu Zhang</i>	

Improving Optical and Electronic Performance of Monolayer Silicon Carbide Via Metal Doping	827
<i>Junfeng Li, Yanlong Tang, Siyuan Xu, Tao Lin, Tuobei Sun, Huaiyu Ye</i>	
Study on Electromigration Lifetime of Ni/solder/Cu Sandwich Structure with Different Pb Content.....	831
<i>Jiang Xie, Baojun Qiu, Hongqin Wang, Zhao Yan, Wenyu Suo, Xiaofeng Yang</i>	
Key Factors for the Formation of Intermetallic Compound During Cu-Sn TLPB Process	835
<i>Yuyan Ding, Tao Zhao, Pengli Zhu, Liang Xu, Rong Sun</i>	
Using Stacked Inverse-Reflective Cup Structure to Improve Vertical Light Output and Ambient Contrast Ratio of Light Emitting Diode Display Device.....	840
<i>Chonghui He, Yunlong Zhang, Jiasheng Li, Zongtao Li</i>	
SEM Study on the Mechanism of Electromigration Induced Sn Alloy Solder Joints Failure	845
<i>Qingyi Liu, Tongcheng Du, Fei Su</i>	
Solution to Optimize Warpage Performance for 2.5D Fanout Packaging	851
<i>Yue Jiang, Yang Chen, Fengtian Hu, Dong Han, Jianmin Fang, Guangyao Li, Keqing Ouyang</i>	
Research on PID Parameter Self-Tuning and Feedforward Control of Precision X-Y Motion Platform for Wire Bonding Machine	855
<i>Wen Liang, Huan Rao, Quan Zhou</i>	
Enhancing Properties of Low-Temperature Pressureless Ag Sinter-joining by Optimizing Solvents and Hybrid Particles	860
<i>Yitian Li, Yujian Wang, Haidong Yan, Wanli Li, Jie Zhang</i>	
Study on Cracking Behavior of Sintering Silver Joints Based on Cohesive Zone Model.....	865
<i>Rui Yang, Yanwei Dai, Fei Qin</i>	
Rapid and Low Temperature Cu Particle Sintering for Power Devices with Mixing of MOD Ink and Reductive Additives.....	869
<i>Jianbo Xin, Yue Gao, Quan Sun, Yang Liu, Jing Zhang</i>	
Improve the High-Temperature Reliability of Epoxy Encapsulation with Copper Substrates Through a Copper Thiolate Complex Layer.....	874
<i>Shuaijie Zhao, Chuantong Chen, Motoharu Haga, Minoru Ueshima, Hirose Suzuki, Hiroto Takenaka, Katsuaki Suganuma</i>	
Simulation of Morphology Evolution and Pore Segregation of Ag Sinter Joint at High Temperature.....	878
<i>Ye Wang, Chuantong Chen, Guicui Fu, Bo Wan, Katsuaki Suganuma</i>	
Influences of Bonding Process Parameters on Mechanical Properties of the Micro-LED Device.....	882
<i>Kefeng Wang, Han Zhong, Zehua Chen, Haojie Zhou, Xiaoxiao Ji, Xiuzhen Lu, Luqiao Yin, Jianhua Zhang</i>	
Silver@Expanded Microspheres/Silicone Conductive Composites with Ultra-Low Compression Stress for Electromagnetic Interference Shielding in Electronic Packaging	886
<i>Yingjie Duan, Luhui Zhang, Yong Wang, Yadong Xu, Rong Sun, Yougen Hu</i>	
Rapid Moisture-Responsive Biopolymer Film Actuators.....	890
<i>Yunxia Yang, Dan Li, Fu Guo</i>	
High-Precision Positioning Detection Technology for Large-size Fan-out Panel-level Package Chips.....	894
<i>Zhihang Chen, Xindu Chen, Mingxia Jiang</i>	

On-Chip Substrate Integrated Plasmonic Waveguide Bandpass Filter for Millimeter-Wave Applications.....	901
<i>Tian Yu, Xin Chen, Yaqing Zhou, Zhongliang Liu, Yuwen Hu, Daquan Yu</i>	
Surface Protecting and Particles Removing After Wafer Sawing for Die-To-wafer Hybrid Bonding.....	905
<i>Hao Wang, Ziyu Liu, Wenchao Wang, Hao Zhu, Lin Chen, Qingqing Sun</i>	
Structure Control and Comprehensive Properties Study of UV-Curable Epoxy Resins.....	909
<i>Zuqiang Wang, Jinhui Li, Guoping Zhang, Rong Sun</i>	
Simulation Study on Temperature Field of Packaged High Power GaN Laser Diodes	913
<i>Hui Liao, Chunyan Song, Ningxuan Yang, Rui Wang, Guanghui Tang, Hongyu Ji</i>	
Plasma-Mediated Enhanced Electroless Photoelectrochemical Etching of Gallium Nitride Nanowire Arrays.....	916
<i>Pengfei Yu, Yun Chen, Maoxiang Hou, Xin Chen, Jian Gao</i>	
Effect of Different Defects in Temporary Bonding on Laser Debonding	920
<i>Jieyuan Zhang, Fangcheng Wang, Qiang Liu, Jinhui Li, Guoping Zhang, Rong Sun</i>	
Analysis of the Transformation Characteristics of Primary and Secondary Fusion Switch Matched Instrument Transformer in Flexible Interconnected Distribution Network	924
<i>Li Li-Sheng, Yu Hai-Dong, Wang Bin, Liu Yang, Zhang Shi-Dong, Huang Min</i>	
Interfacial Engineering of ZnO/CdS Heterostructure for Long Cycle Life Li-O ₂ Batteries	929
<i>Congcong Dang, Rouyan Guo, Aidang Shan, Liancheng Zhao, Ming Li, Liming Gao</i>	
Study on the Key Technology in FC-SiP Packaging with 4L ETS Substrate	933
<i>Xiaoyan Li, Xinxin Tong, Hongqiang Yang, Qingfeng Zhao, Guangyao Li, Yang Chen, Jianmin Fang</i>	
UV Light Enhanced Metal-Assisted Chemical Etching of SiC Triangular Nanostructure Arrays.....	937
<i>Yiming Zhong, Yun Chen, Xin Chen</i>	
Thermal Reliability Analysis of M3D Based on Artificial Neural Network in Multi-Physics Field	941
<i>Sixiang Zhang, Zhiyuan Zhu</i>	
Simulation and Performance Test of High Bandwidth PCB Based on Multichannel Vertical Interconnection High Frequency Connector.....	947
<i>Miao Wu, Dong Wang, Kai Jiao</i>	
The Application of Developing Low-Warpage Bonding Pair by Finite Element Analysis.....	952
<i>Yalin Zeng, Yun Bai, Fangfang Niu, Yanting Liu, Kang Li, Guoming Jiang, Jinhui Li, Qiang Liu, Guoping Zhang</i>	
Optimizing Hierarchical 3-D Floorplanning with Simulated Annealing Algorithm.....	956
<i>Liao Chengyi, Zheng Qi, Liu Fengman, He Huimin, Wang Qidong</i>	
Electroless Amorphous Ni-Cu-P Deposit and the Interaction Between Ni-Cu-P Barrier and Sn Solder	962
<i>Jing Xing, Siyuan Xiao, Xiaofu Li, Jinye Yao, Xiangxu Chen, Haitao Ma</i>	
Laser-Induced Processing of Thermal Cloaks Enabling Heat Shielding	967
<i>Guanhai Wen, Jingtao Chen, Lu Yan, Maoxiang Hou, Li Ma, Yun Chen, Xin Chen</i>	
A Novel Low-Temperature Co-Co Direct Bonding for Future 3D Interconnection	971
<i>Xiaoyun Qi, Yan Ma, Chenxi Wang</i>	

Optimizing Surge Current Capability of Small-Signal SBD Device Based on Fan-out Panel Level Packaging	975
<i>Xudong Luo, Dongdong Shao, Kunpeng Ding</i>	
Newly Designed Colloidal Silica for Copper Chemical Mechanical Polishing in Electronic Packaging	978
<i>Jianhang Yin, Jiale Zhang, Haojun Li, Ning Wang, Chuanqi Zhang, Tao Zhao</i>	
FDTD Simulation of Anti-Reflective Performance for the SiO ₂ /PDMS Transparent Packaging Materials	982
<i>Tengda An, Mozhen Wang, Qingwen Liang, Jianxin Jia, Jiale Zhang, Ning Wang</i>	
Micro Solder Defect Inspection Using Infrared Sequence and Deep Learning Omni-Scale CNN	986
<i>Ye Jiang, Zhiyong Liu, Guanglan Liao</i>	
The Low Dk, Df Surface Modification of Silica Filler in the High Speed and High Frequency Applications.....	989
<i>Qianqian Qiang, Xiaomeng Du, Liu Yang, Haojun Li, Tao Zhao, Pengli Zhu, Rong Sun, Ning Wang</i>	
Thermal Resistance Simulation Analysis and Test Research of Wire Bond Ball Grid Array Package	994
<i>Fang Qu, Bin Yan, Zongwei Wang, Zhongxuan Tian, Jian Pang, Guangyao Li, Xuequan Hu, Keqing Ouyang</i>	
The Preparation of High-Quality W-LED Packaged with Sr _{3-x} Al ₂ Si ₃ O ₁₂ :xEu ³⁺ and YAG:Ce ³⁺	999
<i>Junlin Xue, Bin Wang, Liang Yang, Sicheng Yi, Taiping Han, Yan Wang, Chunyan Cao, An Xie</i>	
Full-Spectrum White Light-emitting Phosphor-in-Glass for Blue LED Chips by Adding Green-Emitting CaY ₂ ZrScAl ₃ O ₁₂ :Ce ³⁺ Phosphor.....	1003
<i>Sicheng Yi, Bin Wang, Liang Yang, Junlin Xue, Taiping Han, Yan Wang, An Xie, Chunyan Cao</i>	
Low-Temperature Direct Bonding of Strengthened Glass Chips for Optical Imaging and Co-packaged Optics	1007
<i>Yu Du, Linjie Liu, Xuming Zhang, Chenxi Wang</i>	
A New High-Efficient Burn-in Screening Methodology Applied in Automotive Integrated Circuits Reliability	1011
<i>Yalan Sheng, Yining Gao, Niuyi Sun, Shaobing Lin, Xinyi Lin, Dan Yang, Na Mei</i>	
Effect of Cu Content in the Ni-Cu Under-bump Metallurgy on the Interfacial Reaction Between Ni _{1-x} Cu _x and Sn Solder	1015
<i>Xiaofu Li, Jing Xing, Xiangxu Chen, Jinye Yao, Haitao Ma</i>	
Laser Etching Process of TSV and Reliability Analysis of TSV-Based IC Structure by Finite Element Simulation	1020
<i>Liyuan Zhang, Min Gou, Haoran Ma, Xiaochuan Xia, Hongwei Liang</i>	
A Resonance Suppression Strategy of LCL-Type Grid-connected Inverter Based on Compound Voltage Feedforward	1025
<i>Haichao Yan, Mi Zhao, Min Lu, HongLei Cen</i>	
A New Numerical Algorithm to Estimate the Average Travel Time of Workpiece in Packaging Equipments Or Reliability Testers.....	1031
<i>Niuyi Sun, Dan Yang, Na Mei</i>	

Completely Filling of Through-Silicon-Vias with High Aspect Ratio by High Cavity Physical Vapor Deposition and Electroplating	1037
<i>Manyu Wang, Ke Li, Shuchao Bao, Zhongliang Liu, Yunting Zhu, Jiahui Wang, Qifei Xia, Shaocheng Wu, Daquan Yu</i>	
Failure Analysis for IIIH Leakage on 7nm FinFFT Technology Chip	1041
<i>Shuanshe Chao, Xinyi Lin, Chen Dong, Na Mei, Dan Yang, Xiao He</i>	
First Principle Study of the Adsorption Behavior of 1,2,4-Triazole on Defective Copper Surface	1045
<i>Pengfei Chang, Zisheng Huang, Tao Hang, Ming Li</i>	
Investigation on Silver Nanowire/Resin-Induced Liquid Crystal Polymer Metallization	1050
<i>Yongjiang Zhang, Zhiqiang Lai, Dan Liu, Tao Zhao, Xianwen Liang, Rong Sun, Xianzhu Fu, Ning Wang</i>	
Study on Low Temperature Sintering Mechanism and Performance of Multiscale Silver Paste	1055
<i>Yiping Wang, Dongsheng Yang, Peng Wu, Shang Wang, Yilong Huang, Jiayun Feng, Jiayue Wen, Yanhong Tian</i>	
Design and Implementation of FPGA-Based Digitally Controlled Quadratic Buck Converter	1059
<i>Yanming Zhao, Honglei Cen, Jing Nie, Zichen Liu, Qiang Cai</i>	
Green and High-Efficiency CMP Slurry for Cu Planarization	1063
<i>Jiale Zhang, Ning Wang, Jianhang Yin, Qingwen Liang, Tengda An, Haojun Li</i>	
The Densification Behavior and Microwave Dielectric Properties of the CBS Glass-Ceramics for LTCC Application	1070
<i>Zhaojun Li, Chao Dong, Tingnan Yan, Qinchen Shen, Rong Sun, Dawei Wang</i>	
Preparation and Characterization of Submicron Silver Particles with the Nanoscale Surface Structure for High-Reliability Packaging	1074
<i>Bolong Dong, Le Zhang, Fan Yang, Qihang Zhou, Wenbo Zhu, Jianjun Du, Mingyu Li</i>	
Stress-Strain Analysis and Optimization of TSV Interconnect Structure Parameters Under Thermal Cyclic Load Loading Based on Bp Neural Network	1078
<i>Lilin Wang, Chunyue Huang, Liye Wu, Xiaobin Liu, Xianjia Liu, Huaquan Zhang</i>	
Simulation and Optimization of Large Scale Multiport Power Supply Noise for 2.5D IC	1084
<i>Chenxi Yang, FengWu FengWu, Jiangtao Zhang, Jianguo Zhang</i>	
Compared Study on the Interfacial Reaction of (111)-Oriented Nt-Cu and Polycrystalline Cu with SAC305 Solder	1089
<i>Hong Wei, Zhi-Jie Zhang, Wang-Rong Liang, Xu Zhou, Quan Shi, Xing Gao</i>	
A 3D Crystal Plasticity Finite Element Model for a 3D Package Under Drop Impact	1093
<i>Shijiao Liu, Yujie Cheng, Linhai Gan, Shanwen Hu, Zhikuang Cai, Lu Liu</i>	
Optimization of Stress and Related Parameters of BGA Solder Joint with Void Defect Under Torsional Load	1099
<i>Junjian Li, Chunyue Huang, Shuyi Li, Shupef Yin, Jiahua Liu, Xianjia Liu</i>	
Contrastive Study on Multiple Reflowing in SnAg-Cu/Ni-P Joints by Laser and Reflow Soldering	1105
<i>Xu Zhou, Zhi-Jie Zhang, Hong Wei, Wang-Rong Liang, Quan Shi, Xing Gao</i>	
Effects of Dishing and Annealing Temperature on Wafer to Wafer Hybrid Bonding	1109
<i>Yu Li, Meng Ruan, Li Liu, Zhiwen Chen</i>	

Influence of Bonding Conditions on Low-Temperature Solid-state Bonding of Cobalt Based Nanocones	1113
<i>Silin Han, Zihan Zhou, Hua Hu, Yunwen Wu, Tao Hang, Ming Li</i>	
Warpage Behavior of the Flip Chip Package in Underfill Curing Process: in Situ Characterization and Numerical Simulation.....	1117
<i>Yixuan Fan, Liang Peng, Zhen'An Zhang, Gang Li, Danning Zhao, Zhenguo Zhang, Rong Sun, Pengli Zhu</i>	
Study on the Effects of Surface Hydroxyl of Silica Fillers on the Mechanical Properties of Underfills.....	1122
<i>Zhenguo Zhang, Xuecheng Yu, Leicong Zhang, Yixuan Fan, Danning Zhao, Rong Sun, Gang Li, Pengli Zhu</i>	
Hydrothermally Synthesized Vanadium Diselenide: A Cathode Active Material for Aqueous Zinc-Ion Batteries	1127
<i>Xinxin Wang, Shang Wang, Yan Feng, Xinyang Ma, Jiayun Feng, He Zhang, Yanhong Tian</i>	
A Comprehensive Study on Signal Integrity of Build-Up Film Applied to IC Substrate	1131
<i>Cheng Zhong, Wenbo Chen, Weikun Kong, Shuhui Yu, Jibao Lu, Rong Sun</i>	
A Wire-Less SiC Power Module Using Flip-Chip Sintering Method.....	1136
<i>Yuncan Liu, Haidong Yan, Daoguo Yang, Wangyun Li, Chaohui Liu, Yakun Zhang</i>	
Simplified Evaluation on Cooling Performance of Silicon Microfluidic Interposer	1142
<i>Miao Yu, Min Huang, Jian Zhu</i>	
Investigations on the Batch Fluctuations of an Epoxy Diluent Via Encapsulation Stress Analysis.....	1147
<i>Xiaobin Lin, Yuefang Li, Jin Jia, Xiang Li, Hua Zhong, Zhibin Zeng</i>	
Study on the Interfacial IMCs Growth of nt-Cu/In Solder Joints	1152
<i>Zicheng Sa, Xudong Liu, Shang Wang, Jiayun Feng, Yanhong Tian</i>	
Design and Integration Approach of Low-Inductance Vertical Interconnection Structure for Gallium-Nitride High Electron Mobility Transistors.....	1156
<i>Yinxiang Fan, Haidong Yan, Daoguo Yang, Wangyun Li, Chaohui Liu, Yakun Zhang</i>	
A Thermo-Mechanical Coupled 3D Crystal Plasticity Finite Element Model for CASTIN Solder Alloy.....	1162
<i>Yang Li, Yujie Cheng, Shanwen Hu, Binbin Xu, Lu Liu, Zhikuang Cai</i>	
Effect of Solder Thick on the Interfacial Reaction in Cu/Sn/Ni Solder Joints.....	1168
<i>Wang-rong Liang, Zhi-jie Zhang, Rui-xi Dang, Xu Zhou, Hong Wei</i>	
Investigation on Transient Failure Mode of Asymmetric Trench Gate SiC MOSFET Under Single-Pulse Avalanche Stress	1172
<i>Shaogang Wang, Yanlong Tan, Xu Liu, Shizhen Li, Ke Liu, Wucheng Yuan, Tao Lin, Guoqi Zhang, Paddy French, Huaiyu Ye, Chunjian Tan</i>	
Analysis of Metallization Effects of Pressure-Assisted Cu Nanoparticle Sintering on DBC by Experiment and Nanoscale Simulation.....	1178
<i>Shizhen Li, Jing Jiang, Xu Liu, Shaogang Wang, Zhonghua Zhang, Huaiyu Ye</i>	
Common Failure Phenomenon of Microwave Components/Modules in Quality Inspection and Measures of Process Improvement.....	1184
<i>Sha Tang, Xing Li, Shuanzhu Fang, Zhuohui Zhou, Wuxiong Fei</i>	

Electrodeposition of Copper with Ultra-Large Grains and Good Conductivity	1188
<i>Yuhang Chen, Hongqi Sun, Ming Li, Tao Hang</i>	
Structure Reliability Analysis of Embedded MicroChannel Cooling with PCB Manifold.....	1192
<i>Peijue Lyu, Yuchi Yang, Hongyue Wang, Yiming Zhang, Zhou Yang, Hongxu Wu, Yufen Jin, Wei Wang, Chi Zhang</i>	
Analysis of Torsional Stresses in POP Solder Joints Under Constant Temperature Field Conditions.....	1196
<i>Jiahua Liu, Chunyue Huang, Shupef Yin, Shuyi Li, Jingyi Lan, Xianjia Liu</i>	
A Novel IGZO-TFT Device with High Dielectric Constant Sandwich Structure Gate Dielectric Layer.....	1201
<i>Yan Wang, Taiping Han, Liang Yang, Bin Wang, Junlin Xue, Sicheng Yi, An Xie, Chunyan Cao</i>	
Structural Design and Optimization of Rectifier Module Based on Copper-Clip Bonding Technology	1206
<i>Jinxiu Wei, Yongjie Gao, Miao Cai, Minghui Yun, Mengyuan Liu, D.G. Yang</i>	
Vertical Hexagonal Arrangement Structure - VHAS	1212
<i>Akanksha Sahoo</i>	
A UV-Curing Temporary Bonding Material with High-temperature Survivability	1217
<i>Yanting Liu, Yun Bai, Yalin Zeng, Kang Li, Guoming Jiang, Jinhui Li, Qiang Liu, Xuefan Wang, Guoping Zhang</i>	
Implantable Flexible Temperature Sensor for In-Operando Sensing of Lithium-ion Batteries	1221
<i>Dengji Guo, Weichang Li, Taisong Pan, Yuan Lin</i>	
Investigation of Moisture Influence on Structure and Thermal Conductivity of Epoxy Resin by Molecular Dynamics Simulation	1225
<i>Can Sheng, Tao He, Wenze Zhang, Shizhao Wang, Sheng Liu</i>	
Time-Dependent Dielectric Breakdown of 4H-SiC MOSFETs in CMOS Technology	1231
<i>Yaqian Zhang, Jiarui Mo, Sten Vollebregt, Guoqi Zhang, Alexander May, Tobias Erlbacher</i>	
A Gate Driver Circuit for Crosstalk Suppression of SiC MOSFET in Half-Bridge Configuration.....	1235
<i>Longnv Li, Man Xiao, Lu Wang, Zhongying Chen, Yunhui Mei</i>	
SIP Solder Paste Via Powder Cluster Design Harvest Both Slump Resistance and Temperature Cycling Reliability	1241
<i>Zhengfeng Xu, Jian Wang, Ning-Cheng Lee, Aixia Zheng, Ming Wang, Qiwei Gu</i>	
Design and Characterization of a Novel Low Temperature Wafer Level Bonding Technology	1245
<i>Chunsheng Zhu, Lichao Zhang, Jingxin Zhong</i>	
Research on NonLinear Active Disturbance Rejection Controller for Permanent Magnet Synchronous Linear Motor.....	1249
<i>Huan Rao, Wen Liang, Quan Zhou, Guofu Qiu, YiKun Ren</i>	
In-Situ Observation of Microscale Crack-tip Strain Field Evolution in Underfill with Different Toughening Agents Via SEM-DIC Coupled Method	1254
<i>Xuecheng Yu, Zhenguo Zhang, Gang Li, Pengli Zhu, Rong Sun</i>	
The Investigation of Threshold Voltage Instability of p-GaN AlGaIn/GaN HEMT Caused by the Measurement	1260
<i>Zongqi Cai, Anru Lv, Zhiyuan He, Yijun Shi, Yiqiang Chen, Guoguang Lu, Liye Chen, Qingzhong Xiao</i>	

The Study on Bulging Mechanism of Plastic Packaging Materials for Electronics	1265
<i>Jiabao Gu, Yanhuang Tang, Junhao Liang, Huanxiang Xu, Chengcheng Chen, Zilian Liu</i>	
Development and Prospect of Coaxial Through-Silicon Via in 3D Integrated Circuits	1268
<i>Ma Junkai, Shan Guangbao, Li Guoliang, Liu Zheng, Fan Weihua</i>	
Hansen Solubility Parameter Optimization of Surface Modified Silica Filler in Electronic Packaging Materials	1273
<i>Liu Yang, Haojun Li, Qianqian Qiang, Xiaomeng Du, Tao Zhao, Pengli Zhu, Song Sun, Ning Wang</i>	
Die Shift Simulation in Panel Level Packaging.....	1277
<i>Bin Gu, Jing-En Luan, Daniela Spini, Samuele Zalaffi, Marco Rovitto, Chun-Hao Chen</i>	
Accurate Assessment of Young's Modulus of Sintered Ag Joints by Nanoindentation	1281
<i>Yuning Zhang, Liang Xu, Pengli Zhu, Tao Zhao, Rong Sun</i>	
The Structural Optimization of Heterogeneous Integration System in Display Based on Thermal-Mechanical Behaviors	1286
<i>Sixin Huang, Haohui Long, Jianhui Li, Rilin Shen</i>	
Effect of Different Proportions and Powder Sizes of Sn on the Performance of Cu-Sn TLPB Joints.....	1292
<i>Yuyan Ding, Tao Zhao, Pengli Zhu, Liang Xu, Rong Sun</i>	
A V Band Ball Grid Array Interconnection Design of Ceramic Package with High-Performance.....	1298
<i>Yangfan Zhou, Linjie Liu, Zhizhuang Qiao, Heng Zhang</i>	
Interfacial Reliability Analysis and Structural Optimization of System-In-Package Modules.....	1301
<i>Sixin Huang, Haohui Long, Jianhui Li, Rilin Shen</i>	
Effect of Silane Coupling Agent on the Performance of Electrically Conductive Adhesives	1307
<i>Mengmeng Chen, Liang Xu, Pengli Zhu, Tao Zhao, Rong Sun</i>	
Optimizing Conformal Shielding Scheme with Quantitative Analysis	1311
<i>Zhang Xinyu, Li Jun, Yang Chenglin, Yuan Jian, An Huilin, Zhang Wenwen, Zhou Minghao</i>	
Effect of Additives on Uniformity of Copper Coatings at Electroless Plating Interconnection	1317
<i>Nana Ren, Haoming Liu, Yuyi Zhang, Zhuo Chen</i>	
Understanding Heat Diffusion Solvers for Electronic and Microelectronic Engineers	1322
<i>Bo Gao, Li Zhang, Chunguang Zhang, Yan Ling</i>	
Optimization and Analysis of Constant Acceleration Test Fixture for Large Size Ceramic Shell.....	1326
<i>Hui-Xin Zhang, Jiang-Tao Chen, Bing-Qian Liu, Hang-Zhou Li</i>	
A Study on Warpage Behavior of Underfill in Flip Chip	1330
<i>Xiaohui Peng, Wenji Ai, Yan Pan, Guolin Zhao, Xiaomeng Du, Pengli Zhu</i>	
Study of Flip Ultrasonic Bonding Process with Non-Conductive Paste.....	1334
<i>Haoming Liu, Hengtong Guo, Shimeng Xu, Xiaochen Xie, Pengrong Lin, Yuyi Zhang, Zhuo Chen, Fuliang Wang</i>	
Chlorine and Sulfur Effects on Silver Bonding Wire Reliability.....	1340
<i>Jinzhi Liao, Bisheng Wang, Xi Zhang, Younan Hua, Xiaomin Li</i>	

A Novel Focused Induction Heating Method for the Interconnection Between High-Power Devices and Integrated Circuit Board	1344
<i>Peng Cui, Haosong Li, Fan Yang, Wenbo Zhu, Bo Hu, Mingyu Li</i>	
Effect of Chip Size and Shape on the Thermal Stress and Strain of Sintered Ag Joints During Thermal Cycling	1349
<i>Yuning Zhang, Cheng Zhong, Liang Xu, Pengli Zhu, Tao Zhao, Rong Sun</i>	
The Prediction of the Solder Ball Crack Based on Artificial Neural Network Using S Parameters	1354
<i>Huanpeng Wang, Yuehang Xu</i>	
Optimization of Packaging Process in Ag Sintering for Ultra-Reliable SiC Based Power Electronics	1357
<i>Minglu Xia, Man Kai Cheung Paul, Ziyang Gao, Chun Ho Fan Nelson, Hoi Ping Ng Eric, Wing Kit Cheung Jack</i>	
Design and Characterization of Novel Doped Heterostructured Electromagnetic Shielding Packaging Materials for Current Sensor Chip Applications	1361
<i>Haichao Huang, Shuaipeng Wang, Yanning Chen, Zhen Fu, Yongfu Li, Xiping Jiang</i>	
Impact of Zn Content on Cu/Al Joints with (Cu+Zn+Al) Mixed Particles	1366
<i>Jin Zhou, Guisheng Gan, Jie Luo, Siwen Chen, Hao Yang, Yongchong Ma, Huaishan Wang, Daquan Xia, Weisheng Wang</i>	
Modeling and Simulation of a High Bandwidth Conical 3D Monopole Antenna for 3D IC	1370
<i>Yang Wang, Yudi Ju, Ziyu Liu, Qingqing Sun, Lin Chen, David Wei Zhang</i>	
Study on the Effect of Manual Splitting on Thermal Fatigue Reliability of PBGA Solder Joints	1375
<i>XiaoChuan Xie, GuoBao Tang, JunShuai Chen, YeJun Chen</i>	
A Novel No-Clean Type 5 SAC305 Solder Paste Reflowed Under Air Atmosphere	1379
<i>Jinjin Bai, Xiaoqin Lu, Fen Chen, Yan Liu</i>	
Optimization of Laser-Induced Deep Etching for TGV Fabrication in Fused Silica	1385
<i>Jingli Liu, Chenhui Xia, Xuefei Ming, Chunyan Yin</i>	
Failure Analysis and Modeling of Blind Vias Crack in BGA-PCB Assemblies	1391
<i>Ying Shi, Shaohua Yang, Fugen Wu, Huafeng Dong</i>	
The Influence of Pattern Size on the Profile and Microstructure of Electroplated Copper Pad, Redistribution Layer and Via for Advanced Packaging	1395
<i>Jin-Hao Liu, Li-Yin Gao, Xian-Wei Cui, Yong-Qiang Wan, Zhi-Quan Liu</i>	
Thermal and Reliability Study of Self Propagating Reaction Interconnects in Microsystem Integration	1400
<i>Tao Zhang, Zheng Zhou, Chang Lei Feng, Peifeng Hu, Wei Zhang, Li Yang, JingChao Xia, Peng Wu, Jiang Qian</i>	
A Single-Layer Photosensitive Polymer Material for Temporary Bonding and Laser Debonding	1404
<i>Xuefan Wang, Qiang Liu, Fangcheng Wang, Wenxue Dai, Kang Li, Guoping Zhang, Rong Sun</i>	
Effects of Additive Interactions on Electroplating Profile of IC Substrate Copper Pillars	1408
<i>Xiao Li, Zhe Li, Li-Yin Gao, Rong Sun, Zhi-Quan Liu</i>	
Cu/SiC Heterogeneous Interconnection with High-Frequency Ultrasound at Low-temperature	1414
<i>Hao Yang, Guisheng Gan, Jie Luo, Siwen Chen, Jin Zhou, Yongchong Ma, Huaishan Wang, Daquan Xia, Weisheng Wang</i>	

Prospective Application of Nanotwinned Copper for Damascene Via Filling and Hybrid Bonding.....	1419
<i>Li-Yin Gao, Yong-Qiang Wan, Zhi-Gang Lei, Yu-Xi Wang, Zhe Li, Xiao Li, Zhi-Quan Liu, Rong Sun</i>	
Computational and Experimental Study of a Novel L-Cysteine Hydrochloride Leveler for Copper Electroplated Via Fill in Redistribution Layers	1425
<i>Yu Jiao, Zhe Li, Xing-Quan Liu, Zhi-Quan Liu, Rong Sun</i>	
Electro-Thermal-Mechanical Simulation of a Three-dimensional Stacked Flexible Circuit Interconnects Structure and Its Comparative Analysis	1430
<i>Haoquan Qian, Hongyue Wang, Xiaoyang Mei, Wenhui Zhu, Liancheng Wang</i>	
Research on the Improved FCS-MPC Strategy for Photovoltaic Grid Connection Based on the O-Z Source Inverter	1437
<i>Weiqi Xu, Min Lu, Chen Liu, Jixin Shao</i>	
Simulation of Performance and Reliability of Nanocopper Paste in Power Device Packaging	1443
<i>Tongtong Wang, Liang Xu, Pengli Zhu, Tao Zhao, Rong Sun</i>	
Branched Alumina Filled Epoxy Resin and Finite Element Simulation.....	1448
<i>Xiong Yao, Xiaojian Wang, Yanfang Dong, Rui Zhang, Zhaoxian Zhang, Caihang Liang</i>	
Thermal Analysis of TSV with Design Factors	1454
<i>Seong-Won Seo, Gu-Sung Kim</i>	
Copper Electroplating of Through Silicon Vias (TSV) Using a Series of Nitrogen-Containing Heterocyclic Compounds	1457
<i>Ke-Xin Chen, Li-Yin Gao, Rong Sun, Zhi-Quan Liu</i>	
Reliability Study of Two-Step Plasma-Activated Copper-Copper Direct Bonding in Ambient	1462
<i>Liangxing Hu, Yu Dian Lim, Michael Joo Zhong Lim, Weiyang Miao, Van Quy Dinh, Zhen Xie, Qimiao Chen, Xin Ju, Chuan Seng Tan</i>	
Ad/desorption Mechanism of Amine-Terminated Polyoxypropylene Suppressor in Advanced Acid Copper Electroplating.....	1466
<i>Ning Zhang, Zhe Li, Rui-Xun Wang, Zhi-Quan Liu, Rong Sun</i>	
3D FO Package Technology Using Bridge Die for High Number of Chiplets Integration.....	1472
<i>Jiaming Zhuang, Shangxuan Li, Xc Zhang, Ivan Chen, Bruce Chen, Simon Hsieh, Bohan Yang, C. Key Chung, Xin Xia</i>	
The Influence of Heterogeneous RDL on the RF Characteristic of Millimeter Wave Phased Array Microsystem	1478
<i>Lichang Huang, Mankai Jiang, Xiaobin Xu, Jinxing Chen, Sha Xu, Yunfei Cao</i>	
Reliability Analysis and Evaluation of Epoxy Resin Adhesive for LED Encapsulation	1484
<i>Huanxiang Xu, Jiabao Gu, Gang Zu, Yanhuang Tang, Chengcheng Chen, Zilian Liu</i>	
Electrochemical Simulation of Electrodeposition Growth of Copper in Through Silicon Via (TSV).....	1488
<i>Zeng-Guang Xu, Cheng Zhong, Zhe Li, Rong Sun, Zhi-Quan Liu</i>	
Influence of Zn Content on Properties of Cu/SAC0307+xZn/Al Joint by Ultrasonic-Assisted at Low-temperature	1494
<i>Jie Luo, Guisheng Gan, Jin Zhou, Hao Yang, Yongchong Ma, Siwen Chen, Jiajun Zhang, Daquan Xia, Huaishan Wang</i>	

Comparison of Electroless Plating Interconnection of Different Reducing Agent Systems	1498
<i>Yuyi Zhang, Nana Ren, Haoming Liu, Zhuo Chen</i>	
Condition Monitoring of SiC Power Assembly by Using Time-Series Analysis of Acoustic Emission During Power Cycling Tests	1503
<i>Zheng Zhang, Fu Shimizu, Yasuko Matsubara, Aiji Suetake, Chuantong Chen, Yasushi Sakurai, Katsuaki Suganuma</i>	
Design and Manufacture of Space Transformer for Vertical Probe Card	1508
<i>Fei Pan, De-Xiang Zhou, Jian-Hui Liu, Rui-Feng Sun, Jun Liu</i>	
CPU Socket Interposer Component Level and PCBA Manufacturability Study and Part 2: iNEMI 2023 Board Assembly – CPU Socket Technology Roadmap	1511
<i>Paul Wang, Top Feng, Rocky Wang, Sanjay Dandia, Changwei Liang, Srikant Nekkanty, Simon Szu, Homer Dai, Jasbir Bath</i>	
Thermal Finite Element Simulation of Ultrafine Pitch Chip-To-Wafer Hybrid Bonding.....	1518
<i>Weimin Liu, Ziyu Liu, Yang Wang, Lin Chen, Qingqing Sun, David Wei Zhang</i>	
Optimization of Mason Model in Thin Film Bulk Acoustic Resonators with Extra Passivating Piezoelectric Structures	1523
<i>Bo Wen, Tengda Zhao, Qi Wang, Jianyu Du, Wei Wang</i>	
Orientation-Related Stress Analysis of Nanotwinned Copper in Redistributed Layer for Wafer-level Packaging	1527
<i>Zesong Wang, Cheng Zhong, Peifeng Li, Zhi-Quan Liu</i>	
Effect of Zn Content on the Performance of Cu/SAC0307+xZn/Al Joints with Dual Ultrasound Assistance.....	1532
<i>Yongchong Ma, Guisheng Gan, Jiajun Zhang, Jie Luo, Hao Yang, Jin Zhou, Siwen Chen, Huaishan Wang, Daquan Xia</i>	
Finite Element Simulation Study of the Effects of Kirkendall Voids in IMC Layer on Interfacial Crack and Reliability of Cu–Sn Solder Joint.....	1536
<i>Ming-Sheng Luo, Hong-Guang Wang, Bin Chen, Guang-Chao Lyu, Xin-Ping Zhang</i>	
An Exploratory Study to Achieve Cu Bump Bonding Structures with Assistance of Bimodal-Sized Cu Nanoparticles by Low-Temperature Thermocompression Bonding in Air	1541
<i>Li-Ping Wang, Min-Bo Zhou, Bin Hou, Deng-Wu Zheng, Xin-Ping Zhang</i>	
Ultrasonic-Assisted Soldering of Al Alloy Using a Novel Ni Mesh Reinforced Sn-9Zn Solder.....	1546
<i>Dan Li, Yong Xiao, Huang He</i>	
Analysis of the Influence of Dispensing on the Reliability of CCGA Solder Joints	1550
<i>Xiaodong Chen, Yabing Zou, Tao Lu, Xiao He, Jiahao Liu</i>	
Solder Selection Simulation of IGBT Module Based on Thermal - Mechanical Coupling Field.....	1554
<i>Bowen Liu, Jibing Chen, Maohui Hu, Junsheng Chen, Qianyu Shi, Yifei Hong</i>	
A Novel Band-Pass Filter in Ka Band with SiP Packaging	1559
<i>Junjie Qin, Han Wang, Danyang Chen, Cheng Zhu, Guanglai Wang, Daoguo Yang</i>	
Flexible Cellulose Fibre/silver Fabric for Highly Efficient and Broadband EMI Shielding Via Metal-Organic Decomposition Approach.....	1564
<i>Si-Yuan Liao, Xiao-Yun Wang, You-Gen Hu, Peng-Li Zhu, Rong Sun, Yan-Jun Wan</i>	

Wafer-Level Controllable Graphene Transfer and Electrical Characterization	1568
<i>Lu Cheng, Haopeng Wang, Wenyuan Zhang, Pengkun Chen, Kai Yuan, Yahui Mao, Huaishan Wang, Le Luo, Bin Zhang</i>	
A Novel Ultra-Thin 90° Bent Vapor Chamber for Heat Dissipation in Multi-heat Source Electronic Devices	1574
<i>Jingjing Bai, Yifu Liang, Huarong Qiu, Yincai Zhao, Shiwei Zhang, Fangqiong Luo</i>	
Research on AI-Based Gold Removal Technology for Aviation Connector Cup Cavity Surface.....	1580
<i>Zhang Yongzhong, Song Deru, Li Jiachang, Qin Tianyi, Qie Zhimin, Zhang Ruizhe</i>	
Demonstration of a Wafer-Level Integration for System-on-Wafer Architecture.....	1586
<i>Weihao Wang, Jie Li, Chuanzhi Wang, Rong Cao, Shunbin Li, Zhiquan Wan, Guandong Liu, Qingwen Deng, Ruyun Zhang</i>	
Thermal-Mechanical Reliability and Package Optimization of a dToF Photon Imaging Sensor	1590
<i>Yufeng Ma, Zijian Wang, Cheng Zhu, Han Wang, Fangxian He, Daoguo Yang</i>	
Numerical Study of the Effect of Epoxy Molding Compound Gradation on the Thermo-Mechanical Properties of Package	1595
<i>Xiaoxin Lu, Yu Zhou, Dongdong Ding, Sun Rong, Jibao Lu</i>	
Fabrication of Stretchable and Thermal Responsive Conductive Polymer Composites for Electromagnetic Interference Shielding	1599
<i>Xinyun Xu, Zhen Zhang, Zhiqiang Lin, Yougen Hu, Rong Sun</i>	
Thermal Performance of 2.5D Packaging with the Through Glass Via (TGV) Interposer.....	1603
<i>Jin Zhao, Fei Qin, Zuohuan Chen, Daquan Yu</i>	
Research on Packaging Reliability of LTCC High Density Packaging Substrate with High-CTE.....	1607
<i>Han Li, Xiaojun Zhang, Zhentao Yang, Linjie Liu</i>	
The Effect of Epoxy Molding Compound Dispensing Uniformity on PoP Warpage	1611
<i>Tao Pan, Lin Wu, Isaac Sun, Brian Li, Zhenhui Ren, Changhao Quan, Charles Ahn</i>	
An Accurate Numerical Prediction for the Thermal Conductivity of Thermal Interface Materials.....	1614
<i>Xiaoxin Lu, Jiabin Huang, Nan Cheng, Dongdong Ding, Jibao Lu, Sun Rong</i>	
A Method of ADC Circuit Noise Optimization Based on a Stochastic Resonance Bistable System.....	1618
<i>Zhang Ying, Sun Bo, Guo Chunbing</i>	
The EBG Structure for Mutual Coupling Suppression Between Antenna Units	1623
<i>Xie Dan, Sun Bo</i>	
Research on Optimized Modeling of Package Warping Phenomenon	1628
<i>Lin Wu, Tao Pan, Guozhen Zhu, Xiaofei Sun, Xian Zhang, Aiden Kim, Brandon Chae, Changhao Quan, Hengrong Shi, Charles Ahn, HoonSun Jung</i>	
Effect of Dimension and Defects on the Flexibility of Ultra-Thin Chips for Wearable Electronics.....	1631
<i>Yan Pan, Shuye Zhang, Taiyu Jin, Pengli Zhu, Rong Sun, Kyung-Wook Paik</i>	
Influence of Pin Position on the CDM Peak Current Based on 2.5D and 2D Package	1635
<i>Menghua Wang, Huafeng Li, Dan Yang, Xiao He, Liyi He, Na Mei</i>	
High Density Multi-Chip Embedded Panel-Level Packaging Integration Technology	1638
<i>Xianming Chen, Benxia Huang, Yejie Hong, Lei Feng, Jindong Feng, Guilin Zhu, Gao Huang, Yanlin Dong, Wu Chen</i>	

Structural Analysis of Anisotropic Conductive Film for Liquid Crystal Displays and Semiconductor Packaging Applications	1644
<i>Yadong Xu, Yong Wang, Xuebi Liu, Xi Lu, Zhiqiang Lin, Yanjun Wan, Jianhui Li, Haohui Long, Yougen Hu, Rong Sun</i>	
A Digital Twin Framework of Reflow Soldering Based on a Novel High Dimension Surrogate Model	1648
<i>Fan Ye, Dayuan Jin, Yun Wan, Xin Xie</i>	
A Rapid and Selective Laser Sintering Method of Silver Nanoparticles for High Temperature Electronic Devices Packaging	1653
<i>Guandong Liu, Changhai Wang, Binod Bhandari, Jonathan Swingler</i>	
A Novel Liner Formation Strategy for Double-Sided Through-Silicon-via (TSV) Process	1657
<i>Yigang Hao, Yingtao Ding, Baoyan Yang, Xingling Pan, Zhiming Chen, Ziyue Zhang</i>	
Evaluation and Mechanism Study of a Novel Green Chemical Mechanical Polishing Slurry for Cobalt Interconnects	1661
<i>Zisheng Huang, Pengfei Chang, Xiangzhuo Zhou, Tao Hang</i>	
Warpage Control Method in Fan-Out Wafer Level Packaging with Rectangular Chips.....	1666
<i>Zhengan Yan, Cheng Zhong, Pengcheng Jiang, Chi Ma, Shuang Liu, Dan Zeng, Hong Wang, Zhengxun Hu, Rong Sun</i>	
Modeling and Reliability Characterization of Micro-Coil Springs for Ceramic Grid Array Integrated Circuits	1671
<i>Minghua Zhang, Qi An, Jingming Fei, Jianghao Yu, Hailong Li, Ping Wu, Xiaomin Li, Hefeng Zhang</i>	
Effects of Plasma Treatment on Adhesion and Flow Behavior of Underfill in 2.5D Electric Package	1676
<i>Yuanyuan Yang, Yixuan Fan, Caiping Zhu, Ruoyu Zhang, Jinbao Yang, Jing Chen, Liangjun Xie, Gang Li, Pengli Zhu</i>	
Effect of Metal Ions on Corrosion Behavior of Component Coating in High Temperature and Humidity Environment.....	1681
<i>Haoxi Fu, Rui Deng, Kun Jiang, Chuanjin Deng, Kaibin Chen</i>	
Electrochemical Migration Mechanism of Cu@Ag Composite Preforms by Electromagnetic Compaction for Power Electronics.....	1686
<i>Ziao Li, Weiwei Zhao, Runze Shi, Ziwen Chen, Zhiwen Chen, Li Liu</i>	
Effect of the Toughening Agent and Coupling Agent on the Liquid Epoxy Molding Compound.....	1690
<i>Chunxiang Wei, Mingqiang Liu, Xin Liu, Yanjie Luo, Pengli Zhu, Wenji Ai</i>	
Simulation and Analysis of Temperature Cycle Failure at MLCC Welding End.....	1694
<i>Yao-Yao Liu, Zhen-Tao Yang, Lin-Jie Liu</i>	
Enhancing the Interface Adhesion and Reliability Study of High T _g EMC and Substrate for Multichip Package.....	1697
<i>Bei Wang, Yaqi Cai, Zuyao Liu, Juanjuan Li, Michael He, Lu Liu</i>	
The Effect of Silane Coupling Agent on Viscosity and Mechanical Properties of TIM1	1701
<i>Zhibin Wen, Daifeng Ai, Pingjing Mo, Zhixin Mai, Linlin Ren, Xiaoliang Zeng, Rong Sun</i>	
Correlation Analysis Between Warpage and Metal Thermal Interface Materials Thermo-Mechanical Reliability of Large Size FCBGA.....	1704
<i>Zhuolun Wu, Zhuqiu Wang, Di Qi, Xinyi Lin, Dan Yang, Na Mei</i>	

Optimization Analysis of High-Speed Differential Signal Vias in Package	1708
<i>Jiahua Luo, Huan Yang, Wenjuan Qin, Xiaojian Ma, Weidong Liu</i>	
Fabrication of Ultra-Thin Conformal EMI Shielding Coatings on SiP Modules by Inkjet Printing Technology	1714
<i>Hao Wu, Xiaofei Zhang, Baotan Zhang, Rong Sun</i>	
High-Efficiency and Low-loss Thin Film Lithium Niobate Modulator.....	1718
<i>Peng Yang, Fengman Liu, Siwei Sun, Haiyun Xue, Xiangxu Meng, Liqiang Cao</i>	
The Correlation Between the Microstructure and Mechanical Property of Low Temperature Sintering Nano Ag Paste.....	1723
<i>Qihang Zhou, Fan Yang, Bolong Dong, Jianjun Du, Mingyu Li</i>	
Synthesis and Characterization of Highly-Dispersed Copper Submicron Particles for Low Temperature Sintering Joints	1728
<i>Yi Fang, Fan Yang, Jianjun Du, Bicheng Fu, Fang Qi, Zhengyu Li, Haiyang Cao, Haipeng Xu, Mingyu Li</i>	
Microstructure Evolution and Fracture Mechanism of Sintered nano-Ag Joints on Bare Copper During High Temperature Aging	1732
<i>Qihang Zhou, Fan Yang, Zhipeng Du, Jianjun Du, Mingyu Li</i>	
Optimization of Wafer-Level TTV Using RIE Applied for the Extreme Wafer Thinning	1736
<i>Jinzhua Li, Ziyu Liu, Wenchao Wang, Yang Wang, Lin Chen, Qingqing Sun</i>	
Study on Reliability of Hard-Lap Solder Joints of Microwave RF Coaxial Connectors	1741
<i>Sun Xiaowei, Li Geng, Wu Wenyu</i>	
Stacked Circuit Packaging Method of Multichip SiC MOSFET Power Modules for Electrical Performance Improvement	1746
<i>Hong Chen, Xiangqi Qiu, Pengfei Lu, Song Wei, Ruifeng Li</i>	
Research on the Application of Microscopic Analysis Technology in PCB Inspection and Failure Analysis	1751
<i>Zhenhai Chen, Xingxing Li, Bo Zhou, Xiao He, Wanchun Tian</i>	
A Novel 3D Packaging Technology for High-Reliability Applications.....	1756
<i>Mifeng Liu, Yi Zhou, Jie Dai, Qi Qiao, Jing Wang, Kai Chen</i>	
Investigation on the Effect of the Packaging-Induced Stress on the Reliability of a MEMS Sensor Package.....	1760
<i>Danyang Chen, Yan Ni, Han Wang, Cheng Zhu, Junjie Qin, Daoguo Yang</i>	
Effects of Ge Addition on the Growth of Interfacial Ni ₃ Sn ₄ IMC in the Sn58Bi/Ni Solder Joint: First-Principles and Experimental Investigations	1765
<i>Shasha Zhang, Ziting Ye, Yuhang Wei, Bo Sheng, Zhaoteng Dong, Bing Zheng, Xiuchen Zhao</i>	
Collaborative Optimization of Multi-Energy Complementary System Via Game Theory	1771
<i>Tongqing Song, Haotian Tang, Guo Tao, Ling Qin, Shenghong Ju</i>	
Characterization and Modeling of Interface Delamination in 3D Stacked Package with Combination of Experimental and CZM Analysis	1777
<i>Cheng Zhu, Wen Yang, Danyang Chen, Junjie Qin, Zijian Wang, Daoguo Yang</i>	

Warpage Analysis and Optimization of Fan-Out Panel-Level Packaging in Hygrothermal Environment	1782
<i>Zijian Wang, Wen Yang, Cheng Zhu, Shangxian Wu, Yan Ni, Daoguo Yang</i>	
Design and Fabrication of a Wafer-Level Interposer for System-on-Wafer Packaging Application	1787
<i>Chuanzhi Wang, Guandong Liu, Weihao Wang, Jie Li, Rong Cao, Ruiqi Luo, Pan Wang, Shunbin Li</i>	
Improved Dielectric Constant and Breakdown Strength of Polyimide with Cyclohexane End Group Via Molecular Engineering Strategy	1791
<i>TingLi TingLi, Jie Liu, Shenghua Tang, Chuanwei Huang, Shuhui Yu, Rong Sun</i>	
Enhanced Energy Storage Performance of $\text{Na}_{0.94}\text{Sm}_{0.02}\text{NbO}_3$ Ferroelectric Ceramics by $\text{Bi}_{0.5}\text{La}_{0.5}\text{Ba}_{2/3}\text{Ta}_{1/3}\text{O}_a$ Doping.....	1796
<i>Yaoyao Yun, Jiaming Xiao, Zhaoquan Zeng, Weiji Zhou, Ling Zhang</i>	
Fabrication of Full Glass Antenna-In-Package by Laser Transmission Welding.....	1800
<i>Yuhua Guo, Yunlong Wang, Qiangwen Wang</i>	
A Study on Transmission Loss of Build-Up Film Applied to IC Substrate	1804
<i>Weikun Kong, Wenbo Chen, Cheng Zhong, Baojin Chu, Baozhong Li, Shuhui Yu</i>	
Optimizing Temperature and Flow Fields of 4H-SiC Epitaxial Growth by Integrating CFD Simulation with Multi-objective Particle Swarm Optimization	1809
<i>Jing Tian, Zhuorui Tang, Hongyu Tang, Jiajie Fan, Guoqi Zhng</i>	
Enhanced Thermal Conductivity of Epoxy Adhesive Films by Filling Surface-Modified AlN	1816
<i>Yuping Xu, PengPeng Xu, Peng Li, Peilin Ma, Jie Yang, Baojin Chu, Suibin Luo, Shuhui Yu</i>	
Prediction of Packaging Induced-Warpage for a 3D Stacked Package with a Cure-dependent Viscoelastic Model for EMC	1821
<i>Han Wang, Junjie Qin, Guanglai Wang, Danyang Chen, Shangxian Wu, Daoguo Yang</i>	
Embedded Wafer-Level Microfluidic Cooling Designs for the System on Wafer Packaging	1826
<i>Jie Li, Guandong Liu, Weihao Wang, Rong Cao, Chuanzhi Wang, Lingling Liu</i>	
Thermal Management Method of Three-Dimensional Integrated Inductors Based on Dielectric-cavity TSV Technology	1830
<i>Wangjun Zhou, Chenbing Qu, Zhiwei Fu, Si Chen, Liwei Wang, Chen Sun</i>	
Research on Board Level Reliability of Mounted Ceramic Package.....	1834
<i>Qian Zhang, Jiang-Tao Chen, Zhen-Tao Yang, Lin-Jie Liu</i>	
Finite Element Modelling of a Piezoelectric MEMS Pressure Sensor Using FreeFem++	1838
<i>Xiyao Du, Peng Zhou, Hao Ren</i>	
Molecular Dynamics Simulation of Copper Paste Sintering for Chip Interconnection.....	1842
<i>Yinyin Luo, Miao Cai, Siliang He, Mengyuan Liu, Jinxiu Wei, Daoguo Yang</i>	
Thermal Stress Field of $\text{Al}_2\text{O}_3/\text{Al-Ni}$ Nanofoil/Ni Solder Joints by Self-propagation Reactions.....	1847
<i>Shengbo Huang, Weiwei Zhao, Zhenyu Liu, Chenru Zhang, Zhiwen Chen, Li Liu</i>	
Study on Micro-Silver Joint Doped with Silicon Carbide Nanowires for Power Electronics	1852
<i>Mu-Lan Li, Shijun Huang, Zehao Chen, Jingwen Liu, Longlong Yan, Cai-Fu Li</i>	

A ReaxFF Molecular Dynamics Study on the Mechanism of Material Removal from 4H-SiC Substrate in Chemical Mechanical Polishing	1856
<i>Lianghao Xue, Zhiqiang Tian, Bing Gao, Sheng Liu</i>	
A Digital Image Correlation Study on the Microstructure and Strain Behavior of Electroplated Nanotwinned Copper as Interconnection Material	1860
<i>Zhiqiang Zhang, Peifeng Li, Rong Sun, Zhi-Quan Liu</i>	
The Adhesive Strength Measurements and Analysis of Phase Change Thermal Interface Material	1864
<i>Min Yang, Junhong Li, Yunsong Pang, Xiaoliang Zeng</i>	
Design of a Fuzzy Decoupling Control System for Indoor Environments	1868
<i>Zichen Liu, Honglei Cen, Qiang Cai, Min Lu, Jing Nie, Yanming Zhao</i>	
Reliability Influence of Solder Joints on Gold Plated Carriers.....	1873
<i>Linjiang Tang, Minghua Zhang, Jun Wang, Yuan Yao, Qian Du</i>	
Accurate Identification of Viscoelastic Constitutive Equation of Thermal Interfacial Materials	1877
<i>Yu Zhou, Xiaoxin Lu, Shengchang Ding, Sun Rong, Jibao Lu</i>	
IMC Growth and Microstructure Evolution of Co13%P/SAC/Co-13%P Solder Joint Under Thermal-Electrical Coupling Fields	1881
<i>Jing Rong, Donghua Yang, Lei Guo, Jie Hu, Weiguo Xiang, Kailun Hu, Chunhong Zhang, Huaping An</i>	
Design and Fabrication of SFQ Chip Flip-Chip Interconnection Based on Silicon Bumps	1885
<i>Kun Li, Gaowei Xu, Yang Huang, Hanlin Zhou, Wenbo Zhao, Kelaiti Xiao, Hui Dong, Xiaoming Xie</i>	
Investigation and Optimization of an Integrated Electrooptic Modulator Driver with a High Bandwidth Package for High Speed Optoelectronic Interconnection	1890
<i>Yu Ban</i>	
A Ka Band Tile T/R Module Based on Silicon Packaging	1894
<i>Qiangwen Wang, Yuhua Guo</i>	
Prediction of Bonding Strength for Sintered Ag/DBA Joints Based on Cohesive Zone Model	1898
<i>Libo Zhao, Yanwei Dai, Fei Qin, Qiang Jia</i>	
Influence of Voids in Solder Layer on the Reliability of the IGBT Die Attached Interconnection Under Temperature Shock	1902
<i>Danlei Jiang, Longzao Zhou, Fengshun Wu, Liguang Ding, Kewei Li, Xuemin Li</i>	
Wafer-Level Sn-Ag-Cu/SiO ₂ Transient Liquid Phase Hybrid Bonding (TLP-HB) Technology	1908
<i>Shuai Zhang, Hairong Mao, Hongbo Xu, Lingfang Zeng, Guang Chen, Yuanpeng Zeng</i>	
Effect of Temperature on Diffusion of Aluminum Droplets to Silicon Carbide After Embedding Atoms on the Surface	1912
<i>Yi Lv, Sheng Liu</i>	
Complicated-Trajectory Compartment EMI Shielding in SiP Modules by Dispensing Technology.....	1916
<i>Xiaofei Zhang, Hao Wu, Baotan Zhang, Rong Sun</i>	
Failure Analysis and Improvement Research on Flexible Termination Multilayer Ceramic Capacitors.....	1920
<i>Rui Cao, Yaning Wu, Dandan Zhou, Xilu Hou, Lei Duan, Hengjing Zhu</i>	

A Low Power Consumption Fractal Microchannel Heat Sink Based on Hierarchical Ribs	1925
<i>Yongjin Wu, Changbei Ma, Jiangbo Luo, Yunnan Sun, Dongdong Xie, Guifu Ding, Kai Wang, Yan Wang, Zhuoqing Yang, Shengnan Shen</i>	
Failure Analysis and Reliability Improvement of Large-Size Parallel Seam Welding Package	1930
<i>Yaning Wu, Rui Cao, Xu Wang, Jun Zhang, Baoming Gong, Yuyan Xiang</i>	
Hybrid Integrated Packaging of an Optical-To-microwave Converter	1935
<i>Wu Yilong, Lyu Xiaomeng, Li Yaru, Zhang Jiaming, Zhao Mingxiao, Xu Weihua, Li Wen, Yu Zengxi</i>	
Design Hydro-Solar-Wind Multi-energy Complementary System Via Multi-Objective Optimization	1939
<i>Haotian Tang, Tongqing Song, Guo Tao, Ling Qin, Shenghong Ju</i>	
Design of Inductor Winding Structure Based on Non-Uniform Distribution of Magnetic Flux Density	1945
<i>Yiyi Bao, Xiangnan You, Yunyan Zhou, Wenwen Zhang, Fengze Hou</i>	
High-Throughput Screening Modeling for Exploring Low-k Dielectric Constant Crystals.....	1950
<i>Zikang Guo, Yunwen Wu, Hongwei Su, Qing Huang, Shenghong Ju</i>	
A Novel Lead-Free NaNbO ₃ -based Relaxation Ferroelectric Ceramics for Energy Storage Application	1955
<i>Jiaming Xiao, Yaoyao Yun, Xinhong Cai, Weiji Zhou, Zhaoquan Zeng, Hongwei Li, Baoqing Li, Lei Niu, Ling Zhang</i>	
Thermal Reliability Analysis of High-Power Terahertz Traveling Wave Tube	1961
<i>Shuanzhu Fang, Mengyao Tang, Jun Luo, Zhizhe Wang, Hongfeng Lv, Kun Jiang</i>	
Glycine-Modified Boron Nitride/Epoxy Composites with High Thermal Conductivity and Low Coefficient of Thermal Expansion.....	1965
<i>Zhen'An Dou, Junyi Yu, Peng Li, Jie Yang, Peilin Ma, Hewen Liu, Suibin Luo, Shuhui Yu</i>	
Study of Residual Stress in Packaging Process on Solder Joint Life Under Thermal Shock	1969
<i>Chang Yu, Pei Chen, Fei Qin, Mingyu Geng, Xiangguo Zhou, Yongjie Hua</i>	
A Review of Program Disturb of 3D NAND Flash Memory	1974
<i>Bojie Lou, Qihao Liu, Zhaogui Zeng, Yongwang Zhou, Ji Zhong</i>	
Research on Characteristics of a High Sensitivity Magnetic Sensor	1979
<i>Shuaipeng Wang, Zhen Fu, Yanning Chen, Xiaofeng Cheng</i>	
A Cooling System Based on Wafer-Level Microfluidic Channels for the System-on-Wafer Packaging Application.....	1982
<i>Rong Cao, Guandong Liu, Jie Li, Weihao Wang, Chuanzhi Wang, Lingling Liu, Yuanxing Duan</i>	
Sacrificial Anode Electroless Plating of Iron on Bi ₂ Te ₃ and Electrochemical Analysis for Thermoelectric Interconnection.....	1986
<i>DeZhu Sun, XiLin Huang, LiMing Zhu, Wei Liu, Xin Deng, XiaoKai Hu</i>	
Study on Grinding of Cu-Ta Interface Based on Molecular Dynamic.....	1991
<i>Zhiqiang Tian, Shizhao Wang, Sheng Liu</i>	
Life Prediction of Solder Interconnects Under Harsh Thermal Cycling from Microstructural Degradation	1996
<i>Wanyu Jiang, Jingwen Xu, Jing Wang, Hao Hu, Wei Zhang, Rong An</i>	

Reliability Prediction of PBGA Solder Joint Under High Temperature Torsional Composite Loading Based on BP Neural Network.....	2006
<i>Shoufu Liu, Chi Zhang, Shuai Zhou, Zhuohao Jiang, Tianjing Li, Xiaofei Zhang, Chi Ma</i>	
Additive Fabrication of 3D Surface Conformal Circuits Using a Modified Screen-Printing Technology	2010
<i>Wenbo Li, Qingzhong Zhou, Tianyu Hou, Shujie Liu, Jianzhu Li, Yujie Li, Hui Guo, Xihan Yu</i>	
Development of High Reflectance Insulating Film Materials for Packaging Semiconductor Optical Devices	2016
<i>Wei-Su Chen, Yun Wang, Shiqiao Huang, Zheng Li, Dandan He, Jianwei Zhang, Evan Twan, Xin Liu, Ziming Chen</i>	
Research on TSV Stress of Ultra-Thin Optical Fingerprint Chip	2020
<i>Jinjin Hu, Chenshan Gao, Lei Liu, Ruitian Chen, Jun Li, Qiangbo Zhang, Huaiyu Ye</i>	
The Reliability Study on Electrochemical Migration Evaluations for Common Substrates in Power Electronics	2023
<i>Mingkun Yang, Donglin Zhang, Chenrui Cao, Tao Xu, Xin Tian, Xiuchen Zhao, Yongjun Huo</i>	
Research on Structure Reliability Design Technology of High Power Ceramic Based Microsystem Package.....	2028
<i>Zhen-tao Yang, Jiang-tao Chen, Fei Yu, De-jian Wang</i>	
Research on Thermal Resistance Simulation and Testing Technology of Ceramic Packaging Package.....	2032
<i>Zhen-tao Yang, Fei Yu, Jiang-tao Chen, Peng Li</i>	
Study on the Effect of Solder Flux on the Reliability of Ceramic Package.....	2037
<i>Zhen-tao Yang, Fei Yu, Jiang-tao Chen, Hao-di Ren</i>	
Die Attach for Microelectronic Packaging: Copper Paste Comparison Between Pressure and Pressureless Techniques	2041
<i>Ran Liu, Zheng Zhang, Masahiko Nishijima, Chuantong Chen, Akio Shimoyama, Hirokatsu Sakamoto, Akihiko Happoya, Katsuaki Suganuma</i>	
Ultrasonic-Accelerated TLPB with Ga-Cu Paste Solder for Low-temperature Electronics Interconnects	2045
<i>Yi Chen, Zhaoxia Zhou, Changqing Liu</i>	
The Microstructure of Cu Joint Soldered with a New Cu Coated Ni Foam Reinforced Sn Composite Solder	2051
<i>Huang He, Kewei Tan, Yingxian He, Lei Zhao, Wen Wang, Yong Xiao</i>	
Highly Conductive Stable Grid Electrode Via Electroplating Ni on EHD-Printed Patterns.....	2056
<i>Jingxuan Ma, He Zhang, Xuanyi Hu, Jiayun Feng, Jiayue Wen, Yanhong Tian</i>	
Analysis of Complex BGA Transition for Equivalent Circuit Modeling.....	2060
<i>Kangrong Li, Yanling Wang, Qiao Yang</i>	
Quantitative Microstructural Data of Bulk Solders and Joints Under a New Framework of MicroStructure Hierarchy Descriptor (μ SHD)	2065
<i>Kaiwen Zheng, Zhiheng Huang, Min Xiao, Yuezhong Meng, Hui Yan, Yang Liu</i>	
Simulation on Microstructural Evolution Under Electromigration in Backside Power Delivery Network.....	2071
<i>Xin Zeng, Zhiheng Huang, Min Xiao, Yuezhong Meng, Hui Yan, Yang Liu</i>	

Meso-Scale Crystal Plasticity Modeling of Sintered Silver Nanoparticles in Typical Interconnected Structures.....	2077
<i>Xu Long, Kainan Chong, Chao Chang, Yutai Su</i>	
A Novel UV-Curable Modified Epoxy Resin with High Glass Transition Temperature and Comprehensive Properties.....	2082
<i>Yexin Zhang, Xialei Lv, Jinhui Li, Guoping Zhang, Rong Sun</i>	
Stealth Dicing of SiC Using Femtosecond Laser Bessel Beam.....	2087
<i>Shaowei Li, Pei Chen, Fei Qin, Senyu Tu, Kunzhou Wu</i>	
Research on p-GaN/AlGaN High Sidewall Verticality and Low Damage Etching Applied to Enhanced GaN HEMTs Devices	2091
<i>Xiaoxiao Gao, Yi Huang, Shile Xiang</i>	
Research on Energy Conversion Benefits of Hybrid Wind Power and Concentrating Solar Power System Based on Time-Of-use Electricity Price.....	2096
<i>Hong Zhang, Yannan Chen, Yujie Gao, Mi Zhao, Hongkun Wang, Zhenhua Lei</i>	
Simulation Study of Silicon Carbide Scratching Process with Double Diamond Abrasive	2101
<i>Kunzhou Wu, Pei Chen, Fei Qin</i>	
The Influence of Total Dose Irradiation and Annealing Experiments on Three Types of SiC Power Devices	2107
<i>Jie Jiang, Shengdong Hu, Yijun Shi, Liye Cheng, Zhiyuan He, Qingzhong Xiao, Wei Zeng, Hao Wu, Caixin Hui</i>	
Research of 3D-TSV Crystal Plastic Constitutive and Optimization of Electroplated Copper Filling.....	2114
<i>Kaihong Hou, Zhengwei Fan, Xun Chen, Shufeng Zhang, Dianlong Yu, Yashun Wang</i>	
A Lossy Filter Using Quarter-Mode Substrate Integrated Waveguide and Coplanar Waveguide.....	2120
<i>Shihao Xie, Guohui Li, Jing Zhang, Qitian Jiang, Yinchuan Xiao</i>	
Effect of Current on the Growth of Intermetallic Compounds in Sn-3.0Ag-0.5Cu Solder Joints	2124
<i>Bofeng Li, Jundong Wang, Yao Yao</i>	
Design Strategies of Nanofillers in Photosensitive Polyimide Nanocomposites.....	2128
<i>Tao Wang, Jinhui Li, Fangfang Niu, Guoping Zhang, Rong Sun</i>	
Enhancing the Thermal Stability of Ni UBM Through Introducing High-Density Nano-Twins.....	2132
<i>Yang Wu, Song Pan, Ben Wang, Zhijie Zhang, Leida Chen</i>	
Influence of Cu Nanoparticles on IMCs Between Sn/Cu Joint During Isothermal Stage of Soldering.....	2136
<i>Shengyan Shang, Tianyu Xiao</i>	
Effects of TiO ₂ Nanoparticles on Growth Behavior of IMCs Between Sn/Cu Joint During Isothermal Stage of Soldering	2140
<i>Tianyu Xiao, Shengyan Shang</i>	
Study of the Effect of Si/Dia Interface Structure on Heat Dissipation	2144
<i>Yufeng Wu, An Xie, Xiaodong Jian, Xiaofeng Yang</i>	
Research on Short-Term Power Prediction and Energy Storage Capacity Allocation of Wind and Photovoltaic Power Based on Elman Neural Network.....	2149
<i>Rongrong Li, Ruilin Li, Xiqiang Chang, Lijiao Gong, Jinguo Yu, Xuwei Chao</i>	

Synergistic Effect of Current Stressing and Temperature Cycling on Reliability of Low Melting Point SnBi Solder	2155
<i>Zesheng Shen, Yuxuan An, Zishan Xiong, King-Ning Tu, Yingxia Liu</i>	
Development of Low-Loss and Low-Cost Air-Filled Transmission Lines Based on Advanced Glass Wafer-Level Packaging	2160
<i>Cai Jing, Shuyue Wu, Miao Zhang, Daquan Yu</i>	
Study on Reflow Warpage Deformation of High Pin Density BGA Devices Affected by Moisture	2162
<i>Haoyang Xu, Xianliang Lyu, Yicai Wang, Fengshun Wu, Longzao Zhou, Hao Zhou</i>	
Study on Defect Detection and Impact on Heat Dissipation in Nanosilver Substrates.....	2166
<i>Mengyuan Liu, Miao Cai, Yinyin Luo, Jinxiu Wei, Minghui Yun, Daoguo Yang</i>	
Research of Super Fine Gold Wire Bonding	2171
<i>Wei Ting, Han Zongjie, Xia Haiyang, Wang Yuefei</i>	
Characterizing the Radiation Degradation of Metal Can Packaged Bipolar Transistor.....	2175
<i>Mohan Liu, Wu Lu, Chengfa He, Qi Guo</i>	
Design of Spacer in Silicon Carbide Double-Sided Cooling Packaging Based on Multiphysics Finite Element Topology Optimization	2179
<i>Zizhen Cheng, Hongchang Cui, Mengyu Zhu, Hong Zhang, Fengtao Yang, Wenjie Xu, Laili Wang</i>	
Reliability Study of Fine Pitch Cu-Sn Micro-bump Structure Electromigration Test by Finite Element Simulation	2185
<i>Zheqi Xu, Qian Wang, Lin Tan, Kai Zheng, Yikang Zhou, Jian Cai</i>	
Research on Acceleration Test Model and Parameter Determination Method of Integrated Circuit.....	2190
<i>Chuanjin Deng, Wenjie Zha, Kaibin Chen, Hongfeng Lv</i>	
The Effect of Etching Lead Frame on QFN Package Delamination.....	2195
<i>Yun Li, Tina Li</i>	
Full Ni ₃ Sn ₄ IMC Interconnects Prepared by Current Driven Bonding (CDB) Method.....	2199
<i>Zhikai Chen, Peng Liu, Jing Ren, Mingliang Huang</i>	
Finite Element Analysis of Board-Level Drop Reliability of WLCSP Solder Joints with Eutectic Sn-Bi, Hybrid Sn-Bi/Sn-Ag-Cu and Sn-Ag-Cu Solders.....	2205
<i>Zhiyi Wang, Lin Zhu, Mingliang Huang</i>	
Collapse Behavior and Interfacial Reaction of Cu-Cored Solder Balls Experienced Multiple Reflows.....	2210
<i>Mingqi Yuan, Lin Zhu, Mingliang Huang</i>	
Optimal Design of the Stress-Buffering Structure in MEMS Resonant Accelerometer Package.....	2216
<i>Bie Xiaorui, Xiong Xingyin, Wang Zheng, Yang Wuhao, Li Zhitian, Zou Xudong</i>	
Application of ANSYS Sherlock in the Fatigue Lifetime Evaluation of Board Level Solder Joint	2221
<i>Mengke Yang, Qiuxi Li, Xiaowei Wang, Zhiyun Chen, Xiaoying Jiang, Queenie Zheng Zhang, Biao Tan</i>	
Reliability Evaluation of Sintered AgNPs Strength Degradation: Influence of Microstructural Evolution During Thermal Aging.....	2226
<i>Zhaoxi Wu, Yutai Su, Chao Duan, Xiaoran Cheng, Xu Long</i>	

Electromigration-Induced Failure Behavior of Low-temperature Cu/Sn-57Bi-1Ag/Cu Solder Joints.....	2230
<i>Li Li, Shengbo Wang, Junlin Chen, Mingliang Huang</i>	
Microstructural Evolution and Thermal Fatigue Reliability of Sn-Ag-Cu/Sn-Bi-Ag Hybrid BGA Solder Joints Assembled by Low-temperature Soldering.....	2235
<i>Shanhong Liu, Jing Ren, Mingliang Huang</i>	
Wafer Bumping of Sn-Ag Micro-bumps with High Coplanarity.....	2239
<i>Na Li, Feifei Huang, Yan Yan, Fengming Hu, LiPeng Zheng, Mingliang Huang</i>	
Investigation on the Influence of Frame Structure on Substrate Stress in IGBT Modules	2243
<i>Xiaodong Li, Helong Li, Dingyi Wang, Nian'An Pan, Zhongbiao Zhang</i>	
Simulation of Crack Initiation and Propagation in Solder Layer of IGBT Module Under Temperature Shock in 3D Model Based on Phase Field Method	2247
<i>Jiaolong Qin, Fengshun Wu, Longzao Zhou, Liguang Ding, Hui Liu, Yuan Xiang</i>	
A Stress Evaluation Approach for the Silicon with nano-TSVs by Raman Spectroscopy.....	2253
<i>Luchao Wu, Ziyu Liu, Jun Wang</i>	
Low-Noise Design for Power Delivery Network in 2.5D Integrated Microsystem.....	2258
<i>Yanling Wang, Qiao Yang, Liang Zhao, Baoxia Li</i>	
Transmission Structures Using Parylene C and TSV for Silicon-Based Low-loss and Low-profile Heterogeneous Integrations at Ka-Band.....	2262
<i>Qi Wang, Bo Wen, Lang Chen, Wei Wang, Yufeng Jin</i>	
Study on Effect of Sintering Temperature on Decomposition Process of Organic System and Evolution of Sintered Tissues.....	2266
<i>Liang Wang, Hao Li, Wenjie Xu, Fengtao Yang, Zizhen Cheng, Laili Wang</i>	
Preparation of Nano-Foam Sheet and Its Application in High Temperature Packaging of Power Chips.....	2271
<i>Hongqiang Zhang, Changhao Yin, Jiahe Zhang, Siliang He, Wei Guo</i>	
Study on Energy Management Strategy for Optical Storage Microgrid Considering Dynamic Load Fluctuation.....	2274
<i>Fuyuan Yao, Xin Zhang, Xiqiang Chang, Meng Lin, Lijiao Gong, Weiji Zhou</i>	
Case Analysis on the Fracture of Deformed Leads of the Ceramic Flat Package.....	2280
<i>Zhibin Wang, Jiajia Sun, Guangyao Li</i>	
Comparative Analysis of Different Microfluidic Cooling Technologies for High Performance Chips	2283
<i>Jianyu Feng, Chuan Chen, Rong Fu, Liqiang Cao</i>	
A Micro-Hotplate for MEMS Gas Sensor Wafer Level Packaging	2287
<i>Zhaohua Zhang, Xuewei Zhao, Deyan Wang, Guotao Duan, Chaoyang Xing</i>	
Integrated Data Acquisition Module Based on CPO Packaging.....	2291
<i>Xiaomeng Lv, Li Xibin, Chen Shaoyong, Weihua Xu, Liu Yangzhi, Yilong Wu, Zhu Yunke, Zhou Tao</i>	
The Prediction of Orthotropic Material Properties for RDL Based on Effective Modeling and CNN	2294
<i>Wang Haozhou, Fu Zhao, Wang Jun</i>	
The Crack Propagation Analysis in an IGBT Package Under In-Service Conditions by VCCT.....	2301
<i>Zhao Fu, Hao-Zhou Wang, Jun Wang</i>	

A Novel Approach to 3D Stacking of Power Chips with Hot-Via Interconnections	2306
<i>Wenhan Chang, Huijie Ye, Qian Lu, Jian Zhang, Qingmin Wu, Qifen Cheng, Rongqing Xu, Weiwei Xiang</i>	
Coupling Effect of Electromigration and Joule Heating Induced Failure in Advanced Packaging	2310
<i>Yifan Yao, Yuxuan An, King-Ning Tu, Yingxia Liu</i>	
Heat Dissipation Technology of GaN Power Amplifier Based on Diamond Carrier.....	2314
<i>Naiyi Ji, Hongda Zhou, Lixiang Zhang, Yongzhi Zhao, Zhiqiang Li, XiXi Liu</i>	
Research on Local Heating of Flat Plate Based on Electric Field Distribution Regulation.....	2320
<i>Haojie Liu, Wanrong Wang, Jie Ren, Jiahao Tan, Yan Ye, Shangru Zhou, Kun Li, Gaofeng Zhang</i>	
Double-Decker Silsesquioxane-Doped Benzocyclobutene Functionalized Siloxane Polymer for Low K Materials.....	2325
<i>Jianhao He, Jing Cai, Shichang Tian, Yuanrong Cheng</i>	
Analysis and Modeling of Electrothermal Characteristics of SiC Power Module Based on Planar Interconnection.....	2330
<i>Liang Wang, Yu Liang, Mingzhi Zhao, Tongyu Zhang, Yuchen Wang J, Jin Zhang</i>	
Board Level Underfill Solution for Chiplet Design and Heterogeneous Integration Package	2337
<i>Qingxu Yang, Xiaolong Hu, Jing Lu, Qian Zhang, David Edwards, Huijia Zhu, Lingyun Pang</i>	
Study on Surge Current Characteristic of SiC SBD with Different Solder Layer Structure.....	2341
<i>Zheng Hu, Yinjie Wang, Xiuchen Zhao, Yongjun Huo, Yidan Tang</i>	
A Case Study of Intermetallic Evolutions in a Solder Joint Under Electromigration Using a Novel Experiment-Simulation Combined Approach.....	2346
<i>Haiyang Yuan, Ce Li, Zhaolong Ma, Huizhe Zhang, Mengzhuo Fan</i>	
Study of the ErP Directive EU 2019/1781 on the Ecological Assessment of Three-Phase Asynchronous Motors	2352
<i>Li Peng, Jianpin Jiang, Xiaoxuan Fan</i>	

Author Index